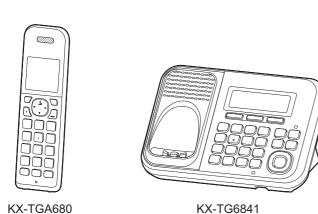# Service Manual

Telephone Equipment

Model No. KX-TG6841BXB
KX-TGA680BXB

Digital Cordless Answering System
B: Black Version
(for Middle Near East)
(for Asia)

KX-TGA680
(Handset)

KX-TG6841
(Base Unit)

Configuration for each model

Model No	Base Unit	Handset	Charger Unit
KX-TG6841	1(TG6841)	1(TGA680)	

Panasonic®

⚠ **WARNING**

This service information is designed for experienced repair technicians only and is not designed for use by the general public. It does not contain warnings or cautions to advise non-technical individuals of potential dangers in attempting to service a product. Products powered by electricity should be serviced or repaired only by experienced professional technicians. Any attempt to service or repair the product or products dealt with in this service information by anyone else could result in serious injury or death.

IMPORTANT SAFETY NOTICE

There are special components used in this equipment which are important for safety. These parts are marked by ⚠ in the Schematic Diagrams, Circuit Board Diagrams, Exploded Views and Replacement Parts List. It is essential that these critical parts should be replaced with manufacturer's specified parts to prevent shock, fire or other hazards. Do not modify the original design without permission of manufacturer.

IMPORTANT INFORMATION ABOUT LEAD FREE, (PbF), SOLDERING

If lead free solder was used in the manufacture of this product, the printed circuit boards will be marked PbF. Standard leaded, (Pb), solder can be used as usual on boards without the PbF mark.
When this mark does appear, please read and follow the special instructions described in this manual on the use of PbF and how it might be permissible to use Pb solder during service and repair work.

- When you note the serial number, write down all 11 digits. The serial number may be found on the bottom of the unit.
- The illustrations in this Service Manual may vary slightly from the actual product.

TABLE OF CONTENTS

1 Safety Precautions

1.1. For Service Technicians

- **Repair service shall be provided in accordance with repair technology information such as service manual so as to prevent fires, injury or electric shock, which can be caused by improper repair work**.
  1. When repair services are provided, neither the products nor their parts or members shall be remodeled.
  2. If a lead wire assembly is supplied as a repair part, the lead wire assembly shall be replaced.
  3. FASTON terminals shall be plugged straight in and unplugged straight out.

- **ICs and LSIs are vulnerable to static electricity.**
  When repairing, the following precautions will help prevent recurring malfunctions.
  1. Cover plastic parts boxes with aluminum foil.
  2. Ground the soldering irons.
  3. Use a conductive mat on worktable.
  4. Do not grasp IC or LSI pins with bare fingers.

2 Warning

2.1. Battery Caution

1. Danger of explosion if battery is incorrectly replaced.
2. Replace only with the same or equivalent type recommended by the manufacturer.
3. Dispose of used batteries according to the manufacture's Instructions.

2.2. About Lead Free Solder (Pbf: Pb free)

Note:
In the information below, Pb, the symbol for lead in the periodic table of elements, will refer to standard solder or solder that contains lead.
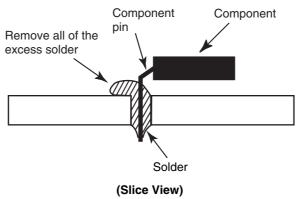
We will use PbF solder when discussing the lead free solder used in our manufacturing process which is made from Tin (Sn), Silver (Ag), and Copper (Cu).

This model, and others like it, manufactured using lead free solder will have PbF stamped on the PCB. For service and repair work we suggest using the same type of solder.
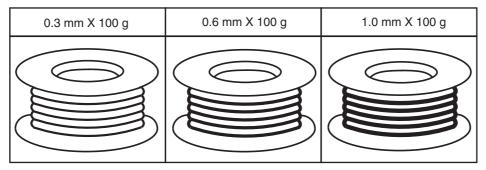
Caution

- PbF solder has a melting point that is 50 °F ~ 70 °F (30 °C ~ 40 °C) higher than Pb solder. Please use a soldering iron with temperature control and adjust it to 700 °F ± 20 °F (370 °C ± 10 °C).
- Exercise care while using higher temperature soldering irons.:
  Do not heat the PCB for too long time in order to prevent solder splash or damage to the PCB.
- PbF solder will tend to splash if it is heated much higher than its melting point, approximately 1100 °F (600 °C).
- When applying PbF solder to double layered boards, please check the component side for excess which may flow onto the opposite side (See the figure below).

Component pin   Component

Remove all of the excess solder

Solder

(Slice View)

2.2.1. Suggested PbF Solder

There are several types of PbF solder available commercially. While this product is manufactured using Tin, Silver, and Copper (Sn+Ag+Cu), you can also use Tin and Copper (Sn+Cu) or Tin, Zinc, and Bismuth (Sn+Zn+Bi). Please check the manufacturer's specific instructions for the melting points of their products and any precautions for using their product with other materials.
The following lead free (PbF) solder wire sizes are recommended for service of this product: 0.3 mm, 0.6 mm and 1.0 mm.

0.3 mm X 100 g	0.6 mm X 100 g	1.0 mm X 100 g

2.3. Discarding of P. C. Board

When discarding P. C. Board, delete all personal information such as telephone directory and caller list or scrap P. C. Board.

3 Specifications

■ **Number of channels:**
 60 Duplex Channels

■ **Frequency range:**
 1.92 GHz to 1.93 GHz

■ **Duplex procedure:**
 TDMA (Time Division Multiple Access)

■ **Channel spacing:**
 1,728 kHz

■ **Bit rate:**
 1,152 kbit/s

■ **Modulation:**
 GFSK (Gaussian Frequency Shift Keying)

■ **RF transmission power:**
 115 mW (max.)

■ **Voice coding:**
 ADPCM 32 kbit/s

	Base Unit	Handset
Power source	AC Adaptor (PNLV226BX0Z, 100–240 V AC, 50/60 Hz)	Rechargeable Ni-MH battery AAA (R03) size (1.2 V 400 mAh)
Receiving Method	Super Heterodyne	Super Heterodyne
Oscillation Method	PLL synthesizer	PLL synthesizer
Detecting Method	Quadrature Discriminator	Quadrature Discriminator
Tolerance of OSC Frequency	13.824 MHz ±100 Hz	13.824 MHz ±100 Hz
Modulation Method	Frequency Modulation	Frequency Modulation
ID Code	40 bit	40 bit
Ringer Equivalence No. (REN)	0.1B	——
Dialing Mode	Tone(DTMF)/Pulse	Tone (DTMF)/Pulse
Redial	Up to 48 digits	Up to 48 digits
Speed Dialer	Up to 24 digits (Phonebook)	Up to 24 digits (Phonebook)
Power Consumption	Standby: Approx. 0.8 W Maximum: Approx. 3.6 W	8 days at Standby, 10 hours at Talk
Operating Conditions	0 °C - 40 °C (32 °F – 104 °F) 20 % – 80 % relative air humidity (dry)	0 °C - 40 °C (32 °F – 104 °F) 20 % – 80 % relative air humidity (dry)
Dimensions (H x W x D)	Approx. 178 mm x 115 mm x 101 mm	Approx. 168 mm x 48 mm x 31 mm
Mass (Weight)	Approx. 340 g	Approx. 130 g

Note:
 • Design and specifications are subject to change without notice.

Note for Service:
 • **Operation range:** Up to 300 m outdoors, Up to 50 m indoors, depending on the condition.
 • **Analog telephone connection:** Telephone Line
 • **Optional headset:** KX-TCA94EX
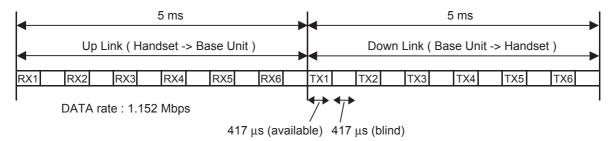
4 Technical Descriptions

4.1. US-DECT Description

The frequency range of 1.92 GHz-1.93 GHz is used. Transmitting and receiving carrier between base unit and handset is same frequency. Refer to **Frequency Table** (P.60).

4.1.1. TDD Frame Format
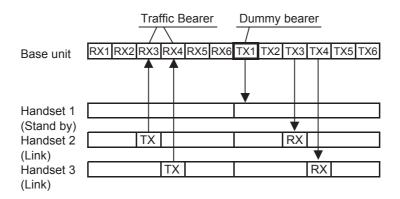
4.1.2. TDMA system

This system is the cycles of 10 ms, and has 6 duplex paths, but maximum duplex communication path is 5 because of dummy bearer use.

In 1 slot 417 μs, the 10 ms of voice data is transmitted.

• **2 - Handsets Link**

Traffic Bearer

A link is established between base unit and handset.

The state where duplex communication is performed.

Handset doesn't make up duplex in no free RF channels because of interference. (*1)

Dummy Bearer

Base unit sends Dummy-data to the all stand-by state handsets.

Handsets receive that data for synchronization and monitoring request from the base unit.

Base unit doesn't send Dummy bearer in no free RF channels because of interference. (*1)

Note:

(*1) It is a feature under FCC 15 regulation and for interference avoidance.

In the case of checking RF parts, it is better in least interference condition.

4.1.3. Signal Flowchart in the Radio Parts

Reception

Base unit:

A voice signal from TEL line is encoded to digital data and converted into a 1.9GHz modulated radio signal by BBIC(IC501).
The RF signal, after which is amplified in BBIC, is fed to selected antenna.

Handset:

As for a handset RF, RF signal is received in one antenna.
BBIC down-converts to 864 kHz IF signal from RX signal and demodulates it to digital data "RXDATA".
BBIC (IC1) converts RXDATA into a voice signal and outputs it to speaker.

Transmission

Handset:

A voice signal from microphone is encoded to digital data and converted into a 1.9GHz modulated radio signal by BBIC(IC1).
The RF signal, after which is amplified in BBIC, is fed to an antenna.
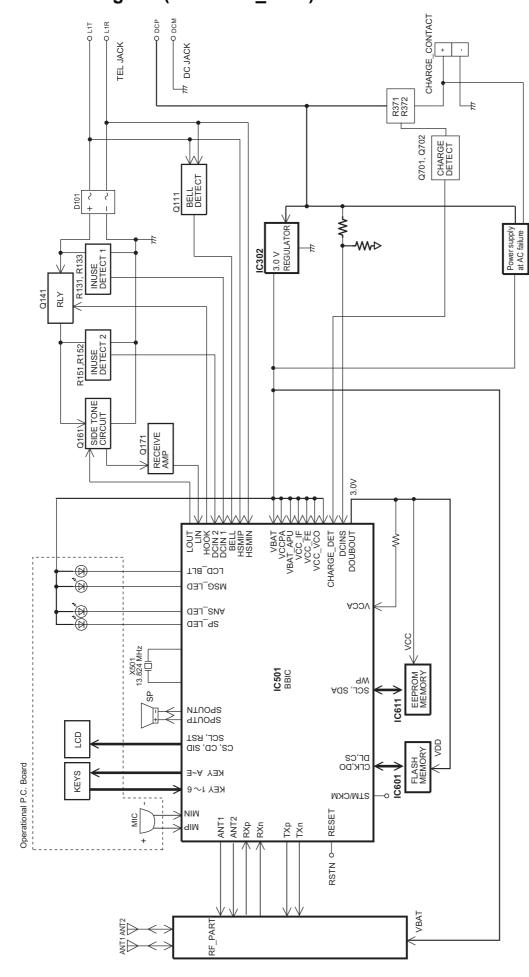
Base unit:

As for a base unit RF, RF signal is received in two antennas.
BBIC (IC501) compares RF signal levels and selects the antenna to be used. Then BBIC down-converts to 864 kHz IF signal from RX signal in the selected antenna, and demodulates it to digital data "RXDATA".
BBIC (IC501) converts RXDATA into a voice signal and outputs it to TEL line.
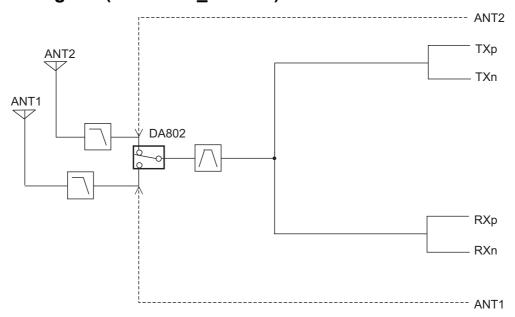
4.2. Block Diagram (Base Unit_Main)

KX-TG6841 BLOCK DIAGRAM (Base Unit_Main)

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4.3. Block Diagram (Base Unit_RF Part)
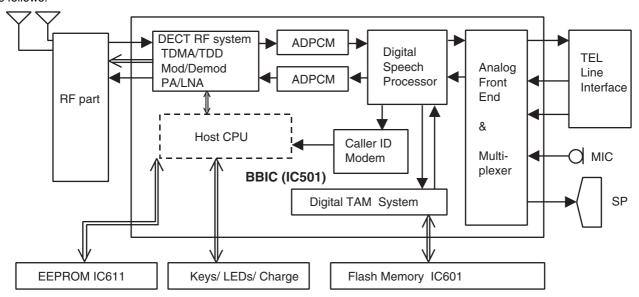
KX-TG6841 BLOCK DIAGRAM (Base Unit_RF Part)

4.4. Circuit Operation (Base Unit)

General Description:

(BBIC, Flash Memory, EERROM) is a digital speech/signal processing system that implements all the functions of speech compression, record and playback, and memory management required in a digital telephone answering machine.

The BBIC system is fully controlled by a host processor. The host processor provides activation and control of all that functions as follows.

4.4.1. BBIC (Base Band IC: IC501)

• **Voice Message Recording/Play back**

The BBIC system uses a proprietary speech compression technique to record and store voice message in Flash Memory.

An error correction algorithm is used to enable playback of these messages from the Flash Memory.

• **DTMF Generator**

When the DTMF data from the handset is received, the DTMF signal is output.

• **Synthesized Voice (Pre-recorded message)**

The BBIC implements synthesized Voice, utilizing the built in speech detector and a Flash Memory, which stored the vocabulary.

• **Caller ID demodulation**

The BBIC implements monitor and demodulate the FSK/DTMF signals that provide CID information from the Central Office.

• **Digital Switching**

The voice signal from telephone line is transmitted to the handset or the voice signal from the handset is transmitted to the Telephone line, etc. They are determined by the signal path route operation of voice signal.

• **Block Interface Circuit**

RF part, LED, Key scan, Speaker, Telephone line.

4.4.2. Flash Memory (IC601)

Following information data is stored.

• **Voice signal**

ex: Pre-recorded Greeting message, Incoming message

4.4.3. EEPROM (IC611)

Following information data is stored.
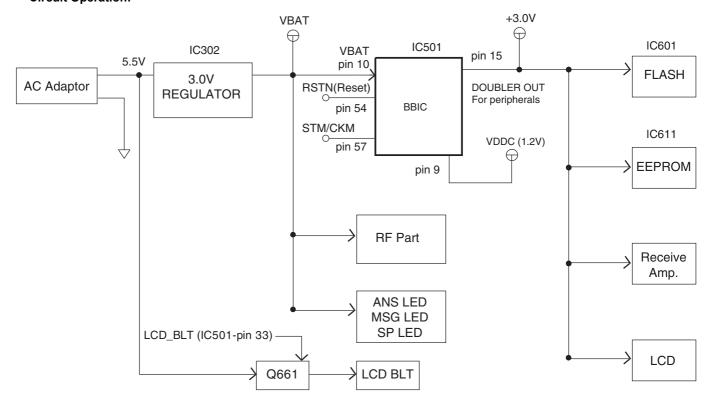
• **Settings**
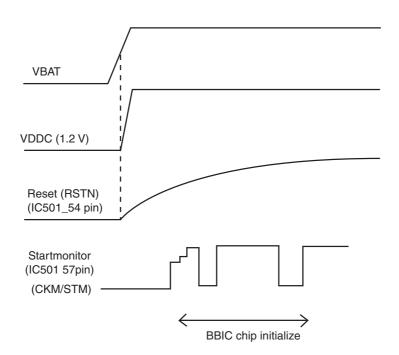
ex: message numbers, ID code, Flash Time, Tone/Pulse

4.4.4. Power Supply Circuit/Reset Circuit

The power supply voltage from AC adaptor is converted to VBAT (3.0V) in IC302. And +3.0V for peripherals and analog part is insulated from VBAT by Doubler of BBIC.

Circuit Operation:

BBIC chip initialize
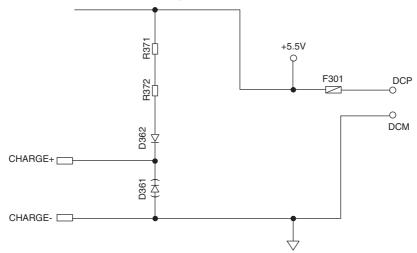
4.4.4.1. Charge Circuit

The voltage from the AC adaptor is supplied to the charge circuits.

R371

R372

+5.5V

F301

DCP

D362

DCM

CHARGE+

D361

CHARGE-

4.4.5. Telephone Line Interface

Telephone Line Interface Circuit:

Function
- Bell signal detection
- ON/OFF hook and pulse dial circuit
- Side tone circuit

Bell signal detection and OFF HOOK circuit:

In the idle mode, Q141 is open to cut the DC loop current and decrease the ring load. When ring voltage appears at the Tip (T) and Ring (R) leads (When the telephone rings), the AC ring voltage is transferred as follows:

T → R111 → C111 → Q111 → BBIC pin 59

When the CPU (BBIC) detects a ring signal, Q141 turns on, thus providing an off-hook condition (active DC current flow through the circuit). Following signal flow is the DC current flow.

T → D101 → Q141 → Q161 → R163 → D101 → P101 → R

ON HOOK Circuit:
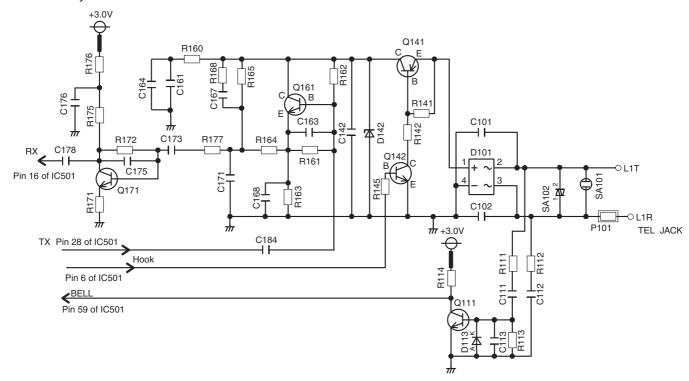
Q141 is open, Q141 is connected as to cut the DC loop current and to cut the voice signal. The unit is consequently in an on-hook condition.

Pulse Dial Circuit:

Pin 6 of BBIC turns Q141 ON/OFF to make the pulse dialing.

Side Tone Circuit:

Basically this circuit prevents the TX signal from feeding back to RX signal. As for this unit, TX signal feed back from Q161 is canceled by the canceller circuit of BBIC.

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4.4.6. Parallel Connection Detect Circuit/Auto Disconnect Circuit

Function:

In order to disable call waiting and stutter tone functions when using telephones connected in parallel, it is necessary to have a circuit that judges whether a telephone connected in parallel is in use or not. This circuit determines whether the telephone connected in parallel is on hook or off hook by detecting changes in the T/R voltage.

Circuit Operation:
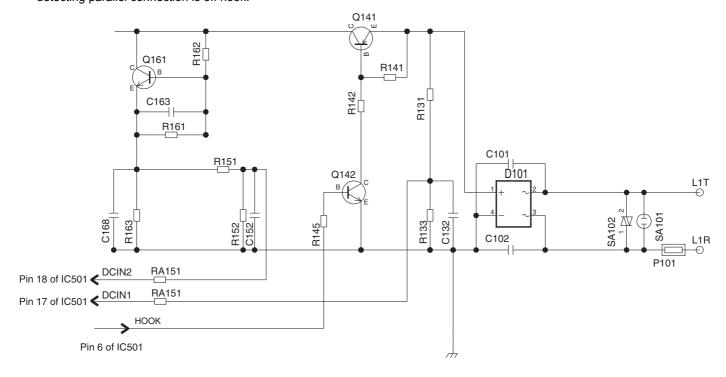
Parallel connection detection when on hook:

When on hook, the voltage is monitored at pin 17 of IC501. There is no parallel connection if the voltage is

0.54 V or higher, while a parallel connection is deemed to exist if the voltage is lower.

Parallel connection detection when off hook:

When off hook, the voltage is monitored at pin 18 of IC501; the presence/absence of a parallel connection is determined by detecting the voltage changes.

If the Auto disconnect function is ON and statuses are Hold, receiving ICM, OGM transmitting, BBIC disconnects the line after detecting parallel connection is off hook.
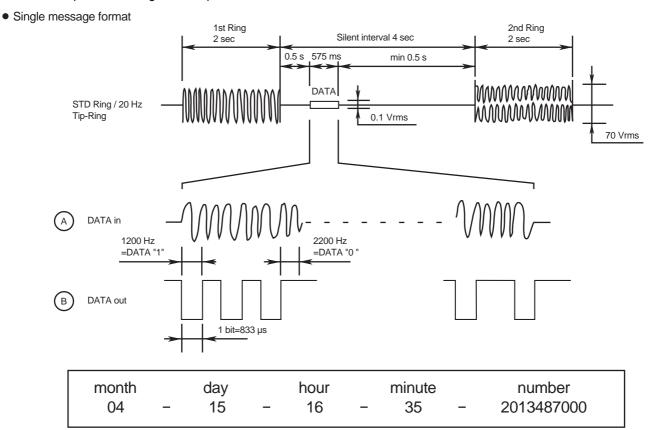
4.4.7. Calling Line Identification (Caller ID)/Call Waiting Caller ID

Function:
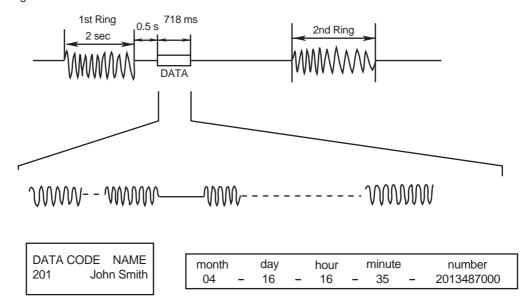
Caller ID

The caller ID is a chargeable ID which the user of a telephone circuit obtains by entering a contract with the telephone company to utilize a caller ID service. For this reason, the operation of this circuit assumes that a caller ID service contract has been entered for the circuit being used. The data for the caller ID from the telephone exchange is sent during the interval between the first and second rings of the bell signal. The data from the telephone exchange is a modem signal which is modulated in an FSK (Frequency Shift Keying) * format. Data "1" is a 1200 Hz sine wave, and data "0" is a 2200 Hz sine wave. There are two types of the message format which can be received: i.e. the single message format and plural message format. The plural message format allows to transmit the name and data code information in addition to the time and telephone number data.

*: Also the telephone exchange service provides other formats.

● Single message format

month		day		hour		minute		number
04	–	15	–	16	–	35	–	2013487000

● Plural message format

DATA CODE	NAME
201	John Smith

month		day		hour		minute		number
04	–	16	–	16	–	35	–	2013487000

Call Waiting Caller ID

Calling Identity Delivery on Call Waiting (CIDCW) is a CLASS service that allows a customer, while off-hook on an existing call, to receive information about a calling party on a waited call. The transmission of the calling information takes place almost immediately after the customer is alerted to the new call so he/she can use this information to decide whether to take the new call.
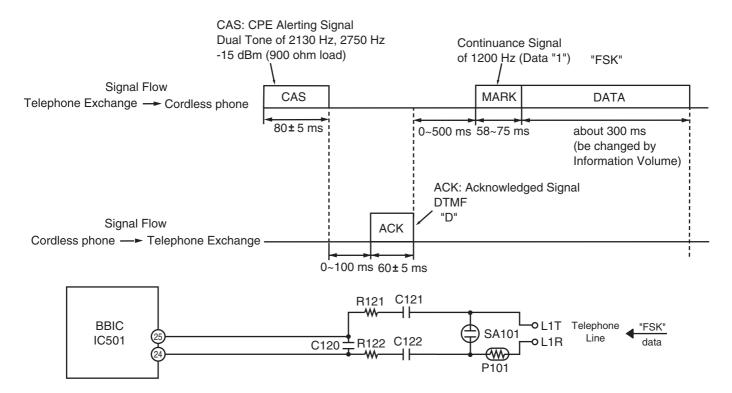
Function:

The telephone exchange transmits or receives CAS and ACK signals through each voice RX/TX route. Then FSK data and MARK data pass the following route.
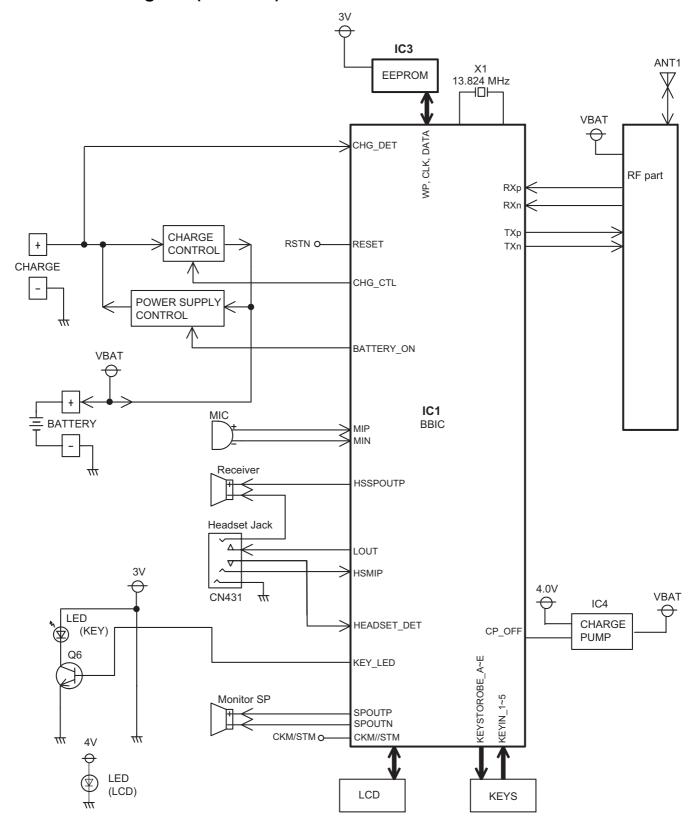
Telephone Line → P101 → C121, C122 → R121, R122 → IC501 (25, 24).

If the unit deems that a telephone connected in parallel is in use, ACK is not returned even if CAS is received, and the information for the second and subsequent callers is not displayed on the portable handset display.

Call Waiting Format

CAS: CPE Alerting Signal
Dual Tone of 2130 Hz, 2750 Hz
-15 dBm (900 ohm load)

Continuance Signal
of 1200 Hz (Data "1")   "FSK"

Signal Flow
Telephone Exchange → Cordless phone

CAS   MARK   DATA

80± 5 ms   0~500 ms 58~75 ms   about 300 ms (be changed by Information Volume)

ACK: Acknowledged Signal
DTMF
"D"

Signal Flow
Cordless phone → Telephone Exchange

ACK

0~100 ms 60± 5 ms

BBIC IC501   25   24

R121 C121
C120 R122 C122
SA101
P101
L1T L1R
Telephone Line   "FSK" data

4.5.   Block Diagram (Handset)

KX-TGA680 BLOCK DIAGRAM (Handset)

4.6. Block Diagram (Handset_RF Part)

KX-TGA680 BLOCK DIAGRAM (Handset_RF Part)

4.7. Circuit Operation (Handset)

4.7.1. Outline

Handset consists of the following ICs as shown in **Block Diagram (Handset)** (P.19).
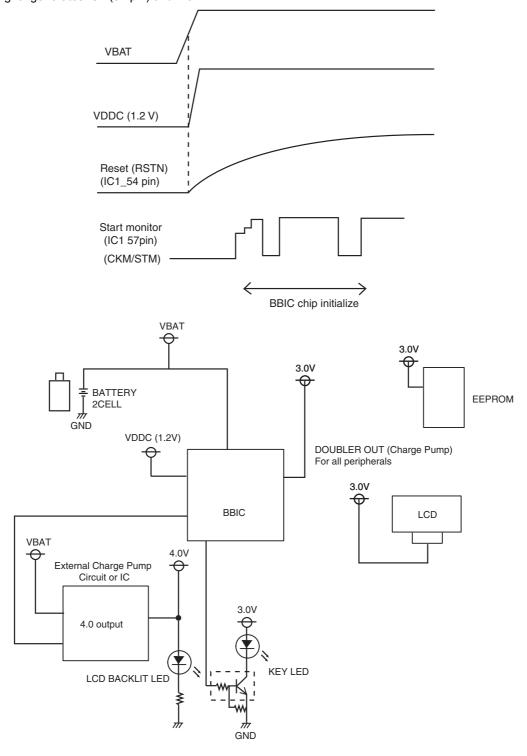
• DECT BBIC (**B**ase **B**and IC): IC1
- All data signals (forming/analyzing ACK or CMD signal)
- All interfaces (ex: Key, Detector Circuit, Charge, EEPROM, LCD)

• EEPROM: IC3
- Setting data is stored. (e.g. ID, user setting)

4.7.2. Power Supply Circuit/Reset Circuit

Circuit Operation:

When powering on the Handset, the voltage is as follows;

BATTERY(2.2 V ~ 2.6 V: BATT+) → F1 → BBC1 (IC1) 10 pin

The Reset signal generates IC1 (54 pin) and 1.8 V.

4.7.3.   Charge Circuit

Circuit Operation:

When charging the handset on the Base Unit, the charge current is as follows;
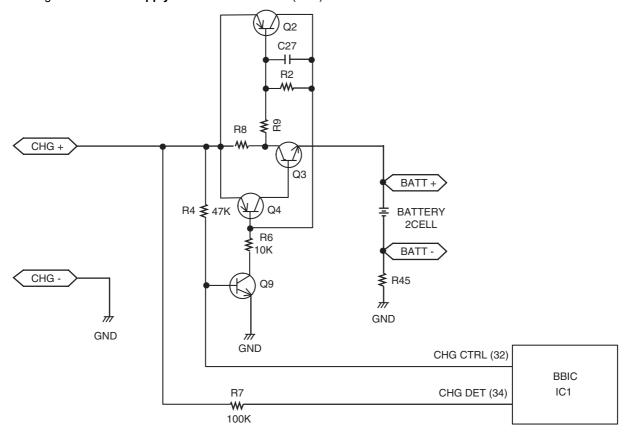
DCP(5.5V) → F301 → R371 → R372 → D362 → CHARGE+(Base) → CHARGE+(Handset) → R8 → Q3 → F1 → BATTERY+...
Battery...

BATTERY- → R45 → GND → CHARGE-(Handset)→ CHARGE-(Base) → GND → DC-(GND)

In this way, the BBIC on Handset detects the fact that the battery is charged.

The charge current is controlled by switching Q9 of Handset.

Refer to Fig.101 in **Power Supply Circuit/Reset Circuit** (P.13).

4.7.4.   Battery Low/Power Down Detector

Circuit Operation:

"Battery Low" and "Power Down" are detected by BBIC which check the voltage from battery.

The detected voltage is as follows;

• Battery Low

Battery voltage: $V(Batt) \leq 2.35$ V ± 50 mV

The BBIC detects this level and "⬚" starts flashing.

• Power Down

Battery voltage: $V(Batt) \leq 2.1$ V ± 50 mV

The BBIC detects this level and power down.

4.7.5.   Speakerphone
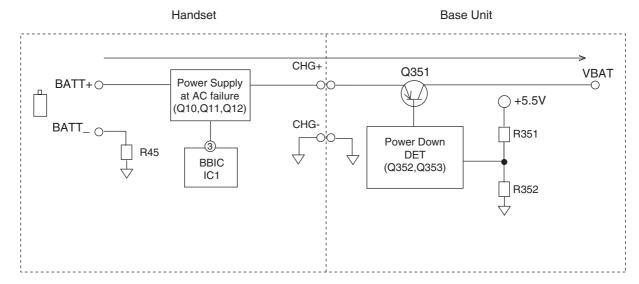
The hands-free loudspeaker at SP+ and SP- is used to generate the ring alarm.

4.8. Behavior of Electric Power Failure

In case that the power from AC adaptor is lost and lose radio waves, BBIC (IC1) turns Q11 ON since handset presumes that base unit's power is falied.

Base unit detects that power voltage of AC adaptor +5.5V is OFF, then turns Q351 ON.

It's possible to use the units during the power failure, supplying power to VBAT of base unit from battery of handset through Q10, CHG terminal and Q351.
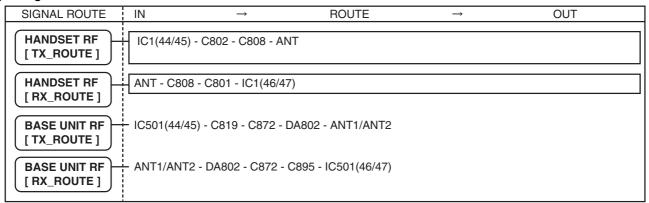
4.9. Signal Route

SIGNAL ROUTE	IN	¤	ROUTE	¤	OUT

HANDSET TX —
HANDSET MIC - C11/13 - RA4 - IC1(22/23) - **<HANDSET_RF_TX_ROUTE>** - ANT. ---

---ANT. - **<BASE_UNIT_RF_RX_ROUTE>** - IC501(46/47 - 28) - C184 - Q161 - Q141 - D101 - P101 - T/R(TEL LINE)

HANDSET RX —
T/R(TEL LINE) - P101 - D101 - Q141 - R165 - R177 - C173 - Q171 - C178 - IC501(16 - 44/45) - **<BASE_UNIT_RF_TX_ROUTE>** - ANT. ---

--- ANT. - **<HANDSET_RF_RX_ROUTE>** - IC1(28/27) - C16 - L8 - HEADSET_JACK(5 - 4) - HANDSET SPEAKER

HEADSET TX —
HEADSET_JACK(2) - C14 - R22 - IC1(25) - **<HANDSET_RF_TX_ROUTE>** - ANT. ---

---ANT. - **<BASE_UNIT_RF_RX_ROUTE>** - IC501(46/47 - 28) - C184 - Q161- Q141 - D101 - P101 - T/R(TEL LINE)

HEADSET RX —
T/R(TEL LINE) - P101 - D101 - Q141 - R165 - R177 - C173 - Q171 - C178 - IC501(16 - 44/45) - **<BASE_UNIT_RF_TX_ROUTE>** - ANT. ---

--- ANT. - **<HANDSET_RF_RX_ROUTE>** - IC1(28) - C16 - L8 - HEADSET_JACK(5)

HANDSET SP-Phone TX —
HANDSET MIC - C11/13 - RA4 - IC1(22/23) - **<HANDSET_RF_TX_ROUTE>** - ANT. ---

---ANT. - **<BASE_UNIT_RF_RX_ROUTE>** - IC501(46/47 - 28) - C184 - Q161 - Q141 - D101 - P101 -T/R(TEL LINE)

HANDSET SP-Phone RX —
T/R(TEL LINE) - P101 - D101 - Q141 - R165 - R177 - C173 - Q171 - C178 - IC501(16-44/45) - **<BASE_UNIT_RF_TX_ROUTE>** - ANT. ---

--- ANT. -**<HANDSET_RF_RX_ROUTE>** - IC1(29/31) - Backside SP

BASE SP-Phone TX —
MIC - C457/C458 - RA452 - IC501 (23/22 - 28) - C184 - Q161 - Q141 - D101 - P101 - T/R(TEL LINE)

BASE SP-Phone RX —
T/R(TEL LINE) - P101 - D101 - Q141 - R165 - R177 - C173 - Q171 - C178 - IC501 (16 - 29/31) - L474/L476 - SPEAKER

INTERCOM HANDSET TO BASE UNIT —
HANDSET MIC - C11/13 - RA4 - IC1(22/23) - **<HANDSET_RF_TX_ROUTE>** - ANT. ---

--- ANT. - **<BASE_UNIT_RF_RX_ROUTE>** - IC501(46/47 - 29/31) - L474/L476 - SPEAKER

INTERCOM BASE UNIT TO HANDSET —
MIC - C457/C458 - RA452 - IC501(23/22 - 44/45) - **<BASE_UNIT_RF_TX_ROUTE>** - ANT. ---

--- ANT. - **<HANDSET_RF_RX_ROUTE>** - IC1(28/27) - C16 - L8 - HEADSET_JACK(5 - 4) - R11 - HANDSET SPEAKER

GREETING RECORDING —
HANDSET MIC - C11/13 - RA4 - IC1(22/23) - **<HANDSET_RF_TX_ROUTE>** - ANT. ---

---ANT. - **<BASE_UNIT_RF_RX_ROUTE>** - IC501(46/47- 73/74) - IC601

GREETING PLAY TO TEL LINE —
IC601 - IC501(73/74 - 28) - C184 - Q161 - Q141 - D101 - P101 - T/R(TEL LINE)

ICM RECORDING —
T/R(TEL LINE) - P101 - D101 - Q141 - R165 - R177 - C173 - Q171 - C178 - IC501(16 - 73/74) - IC601

ICM PLAY TO SPEAKER —
IC601 - IC501(73/74 - 29/31) - L474/L476 - SPEAKER

DTMF SIGNAL TO TEL LINE —
IC501(28) - C184 - Q161 - Q141 - D101 - P101 - T/R(TEL LINE)

CALLER ID —
T/R(TEL LINE) - P101 - C121/C122 - R121/R122 - IC501(24/25)

BELL DETECTION —
T/R(TEL LINE) - P101 - R111/R112 - C111/C112 - Q111 - IC501(59)

Note:

☐ : inside of Handset

RF part signal route

SIGNAL ROUTE	IN → ROUTE → OUT
HANDSET RF [TX_ROUTE]	IC1(44/45) - C802 - C808 - ANT
HANDSET RF [RX_ROUTE]	ANT - C808 - C801 - IC1(46/47)
BASE UNIT RF [TX_ROUTE]	IC501(44/45) - C819 - C872 - DA802 - ANT1/ANT2
BASE UNIT RF [RX_ROUTE]	ANT1/ANT2 - DA802 - C872 - C895 - IC501(46/47)

Note:

☐ : inside of Handset

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5 Location of Controls and Components

Refer to the Operating Instructions.

Note:

You can download and refer to the Operating Instructions (Instruction book) on TSN Server.

6 Installation Instructions

Refer to the Operating Instructions.

Note:

You can download and refer to the Operating Instructions (Instruction book) on TSN Server.

7 Operating Instructions

Refer to the Operating Instructions.

Note:

You can download and refer to the Operating Instructions (Instruction book) on TSN Server.
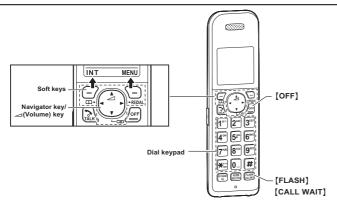
8 Test Mode

8.1. Engineering Mode

8.1.1. Base Unit

> Important:
>   Make sure the address on LCD is correct when entering new data. Otherwise, you may ruin the unit.

Soft keys

Navigator key/ ⌐(Volume) key

Dial keypad

[OFF]

[FLASH]
[CALL WAIT]

H/S key operation

H/S LCD

1). Press 【MENU】.

Phonebook

INT   SELECT

2). Select "Initial setting" using 【▲】 or 【▼】
    then press 【SELECT】 or 【►】.

Initial setting

INT   SELECT

   Select "Set tel line" using 【▲】 or 【▼】
   then press 【SELECT】 or 【►】.

Set tel line

BACK   SELECT

3). Enter "7", "2", "6", "2", "7", "6", "6", "4".
    Note: 7262 7664 = PANA SONI
          (see letters printed on dial keys)

Set dial mode

BACK   SELECT

*

4). Select "Write EEP" using 【▲】 or 【▼】
    then press 【SELECT】 or 【►】.

Service Mode
Read EEP
Write EEP

BACK   SELECT

5). Enter "●", "●", "●", "●" (Address). (*1)

Set Addr.:
●●●● ✳✳ ← Default Data

CLEAR   OK

6). Enter " ✳ ", " ✳ " (New Data). (*1)

7). Press 【OK】 , a long confirmation beep
    will be heard.

Set Addr.:
●●●● ✳✳ ← New Data

CLEAR   OK

8). Press 【OFF】 to return to standby mode.
    After that, turn the base unit power off and then power on.

Set Addr.:
_ _ _ _ _ _

BACK

Note: * To enter "Set dial mode", press 【SELECT】 or 【►】 at " Set tel line".
         It is necessary to turn on the power of base unit.

Frequently Used Items (Base Unit)
ex.)

Items	Address	Default Data	New Data		Remarks
C-ID(FSK) sensitivity	06 E6/06 E5	00/51	00/39 (3 dB up)	00/28 (6 dB up)	When the hex change from 00/51 to 00/39 or 00/28, gain increase by 3 dB or 6 dB.
C-ID(DTMF) sensitivity	07 02/07 01	08/00	0B/4C (3 dB up)	0F/F6 (6 dB up)	When the hex change from 08/00 to 0B/FC or 0F/F6, gain increase by 3 dB or 6 dB.
Frequency	00 07 / 00 08	00/01	-	-	Use these items in a **READ-ONLY** mode to
ID	00 02 ~ 00 06	Given value	-	-	confirm the contents. Careless rewriting may cause serious damage to the computer system.
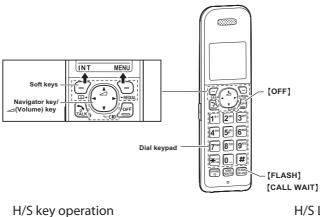
Note:
(*1) When you enter the address or New Data, please refer to the table below.

Desired Number (hex)	Input Keys		Desired Number (hex)	Input Keys
0	0		A	[Flash] + 0
1	1		B	[Flash] + 1
.	.		C	[Flash] + 2
.	.		D	[Flash] + 3
.	.		E	[Flash] + 4
9	9		F	[Flash] + 5

8.1.2. Handset

> Important:
> Make sure the address on LCD is correct when entering new data. Otherwise, you may ruin the unit.

H/S key operation
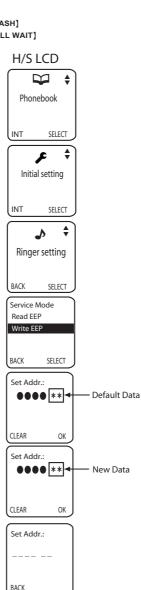
1). Press 【MENU】.

2). Select "Initial setting" using 【▲】 or 【▼】 then press 【SELECT】 or 【►】.

3). Enter "7", "2", "6", "2", "7", "6", "6", "4".
   Note: 7262 7664 = PANA SONI
   (see letters printed on dial keys)

4). Select "Write EEP" using 【▲】 or 【▼】 then press 【SELECT】 or 【►】.

5). Enter "●", "●", "●", "●" (Address). (*1)

6). Enter "＊", "＊" (New Data). (*1)

7). Press 【OK】, a long confirmation beep will be heard.

8). Press 【OFF】 to return to standby mode.
   After that, remove and reinsert the batteries. Press the Power button for about 1 second if the power is not turned on.

H/S LCD

Frequently Used Items (Handset)

ex.)

Items	Address	Default Data	New Data	Possible Adjusted Value MAX (hex)	Possible Adjusted Value MIN (hex)	Remarks
Battery Low	00 12/00 13	00 / 00	-	-	-	
Frequency	00 07 / 00 08	00 / 01	-	-	-	(*2)
ID	00 02 ~ 00 06	Given value	-	-	-	

Note:

(*1) When you enter the address or New Data, please refer to the table below.

Desired Number (hex.)	Input Keys	Desired Number (hex.)	Input Keys
0	0	A	[Flash] + 0
1	1	B	[Flash] + 1
.	.	C	[Flash] + 2
.	.	D	[Flash] + 3
.	.	E	[Flash] + 4
9	9	F	[Flash] + 5

(*2) Use these items in a READ-ONLY mode to confirm the contents. Careless rewriting may cause serious damage to the handset.

9 Service Mode

9.1. How to Clear User Setting (Handset Only)

Handset
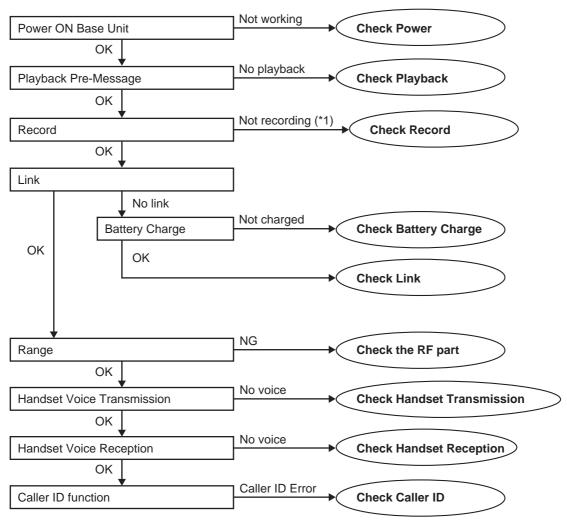
Press ②,⑤,⑧,⓪ simultaneously until a beep sound is heard. Then single handset is initialized.

(The contents of user setting are reset to factory default)

*Usage time is not cleared.

10 Troubleshooting Guide

10.1. Troubleshooting Flowchart

FLOW CHART

Power ON Base Unit	Not working →	**Check Power**
↓ OK		
Playback Pre-Message	No playback →	**Check Playback**
↓ OK		
Record	Not recording (*1) →	**Check Record**
↓ OK		
Link		

Link → OK →
Link → No link → Battery Charge

Battery Charge	Not charged →	**Check Battery Charge**
↓ OK		**Check Link**

Range	NG →	**Check the RF part**
↓ OK		
Handset Voice Transmission	No voice →	**Check Handset Transmission**
↓ OK		
Handset Voice Reception	No voice →	**Check Handset Reception**
↓ OK		
Caller ID function	Caller ID Error →	**Check Caller ID**

Cross Reference:
Check Power (P.33)
Check Playback (P.37)
Check Record (P.34)
Check Battery Charge (P.37)
Check Link (P.38)
Check the RF part (P.40)
Check Handset Transmission (P.45)
Check Handset Reception (P.45)
Check Caller ID (P.45)
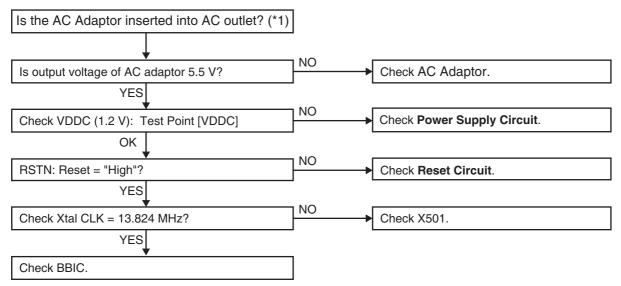
Note:
(*1) When a user claims that the unit disconnects a call right
after the greeting message and no incoming messages can
be recorded, this symptom can not reappear with TEL
simulator in the service center. In this case, try to change
the Auto disconnect activation time and Vox level.
**<How to change the Auto Disconnect activation time
and VOX level>** (P.35) item (A) and (B).

10.1.1. Check Power

10.1.1.1. Base Unit

Is the AC Adaptor inserted into AC outlet? (*1)

Is output voltage of AC adaptor 5.5 V? — NO → Check AC Adaptor.

YES

Check VDDC (1.2 V): Test Point [VDDC] — NO → Check **Power Supply Circuit**.

OK

RSTN: Reset = "High"? — NO → Check **Reset Circuit**.

YES

Check Xtal CLK = 13.824 MHz? — NO → Check X501.

YES

Check BBIC.
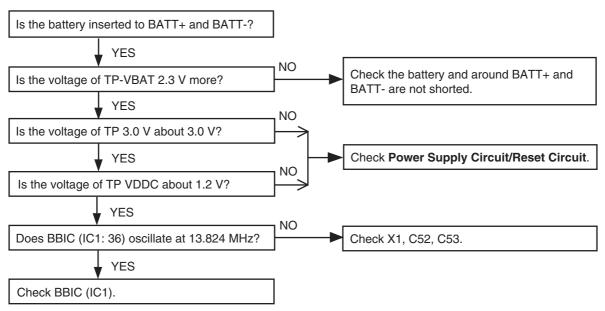
Cross Reference:
  Power Supply Circuit/Reset Circuit (P.13)

Note:
  BBIC is IC501.
  (*1) Refer to **Specifications** (P.7) for part number and supply voltage of AC adaptor.
  (*2) Refer to **Circuit Board (Base Unit_Main)** (P.77).

10.1.1.2. Handset

Is the battery inserted to BATT+ and BATT-?

YES

Is the voltage of TP-VBAT 2.3 V more? — NO → Check the battery and around BATT+ and BATT- are not shorted.

YES

Is the voltage of TP 3.0 V about 3.0 V? — NO → Check **Power Supply Circuit/Reset Circuit**.

YES

Is the voltage of TP VDDC about 1.2 V? — NO →

YES

Does BBIC (IC1: 36) oscillate at 13.824 MHz? — NO → Check X1, C52, C53.

YES

Check BBIC (IC1).
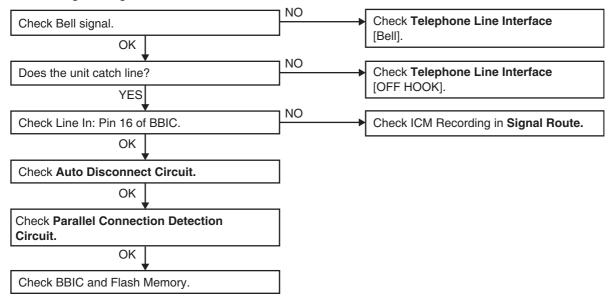
Cross Reference:
  Power Supply Circuit/Reset Circuit (P.21)

10.1.2. Check Record

10.1.2.1. Base Unit

Not record Incoming Message

| Check Bell signal. | NO → | Check **Telephone Line Interface** [Bell]. |

OK ↓

| Does the unit catch line? | NO → | Check **Telephone Line Interface** [OFF HOOK]. |

YES ↓

| Check Line In: Pin 16 of BBIC. | NO → | Check ICM Recording in **Signal Route.** |

OK ↓

| Check **Auto Disconnect Circuit.** |

OK ↓

| Check **Parallel Connection Detection Circuit.** |

OK ↓

| Check BBIC and Flash Memory. |

Cross Reference:
    Signal Route (P.24)
    Telephone Line Interface (P.15)
    Parallel Connection Detect Circuit/Auto Disconnect Circuit (P.16)

Note:
    Flash Memory is IC601.
    BBIC is IC501.

<How to change the Auto Disconnect activation time and VOX level>

A) Auto Disconnect activation time:

Some Telephone Company lines (fiber or cable) ON Hook and OFF Hook voltages are lower than conventional lines, which may cause a malfunction of Auto Disconnect detection. To solve this problem, try changing the Auto Disconnect activation through the procedures below.

1) Press "MENU " key at standby Mode and "#" key.

   Note: The set must power on and be linked.

2) Press "9", "0", "0", "0"," ＊" .

   LCD (H/S)

```
Service ready
:————

BACK
```

3) Press "7","3","1".

```
Service ready
:731_

 CLEAR
```

4) Then enter the below last digit;

last digit		
	"0"	Auto disconnect & CPC : enable[*1] · · · [default]
	"1"	Auto disconnect : enable[*1] CPC : disable
	"2"	Auto disconnect & CPC : disable[*2]

   Note:

(*1) Both Auto Disconnect and CPC don't detect for the first 2 seconds.

(*2) If the "Disable" is selected, even if the parallel-connected telephone is OFF HOOK, the line isn't disconnected.

5) Back to "standby" mode automatically after step 4).
   You can hear beep sound which is a confirmation tone.

B) Vox level:

It makes easier to detect a small voice (caller) by raising the sensitivity of VOX level. Therefore, the recording of TAM is not turned off during detection.

1) ~ 2) are same as (A).

3) Press "5","1","1".

```
Service ready
:5 1 1 ＿


CLEAR
```
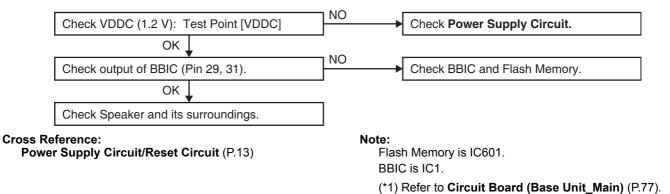
4) Then enter the below last digit;

last digit	"0"	default setting : normal
	"1"	6dB up

5) Back to "standby" mode automatically after step 4). You can hear beep sound which is a confirmation tone.
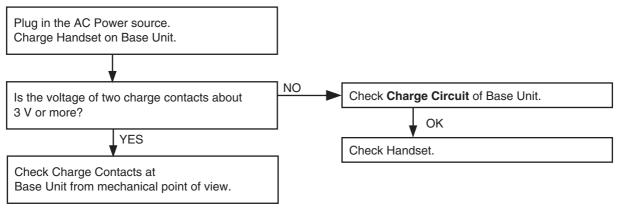
10.1.3. Check Playback

10.1.3.1. Base Unit

| Check VDDC (1.2 V): Test Point [VDDC] | NO → | Check **Power Supply Circuit.** |

OK ↓

| Check output of BBIC (Pin 29, 31). | NO → | Check BBIC and Flash Memory. |

OK ↓

| Check Speaker and its surroundings. |

Cross Reference:
Power Supply Circuit/Reset Circuit (P.13)

Note:
Flash Memory is IC601.
BBIC is IC1.

(*1) Refer to **Circuit Board (Base Unit_Main)** (P.77).

10.1.4. Check Battery Charge

10.1.4.1. Base Unit

| Plug in the AC Power source. Charge Handset on Base Unit. |

↓

| Is the voltage of two charge contacts about 3 V or more? | NO → | Check **Charge Circuit** of Base Unit. |

YES ↓   OK ↓

| Check Charge Contacts at Base Unit from mechanical point of view. | | Check Handset. |

Cross Reference:
Charge Circuit (P.14)

10.1.4.2. Handset

| Is **Check Power** OK? | NO → | **Check Power** of Handset. |

YES ↓

| Is BBIC (IC1: 34) high at charge state? | NO → | Check **Charge Circuit**. |
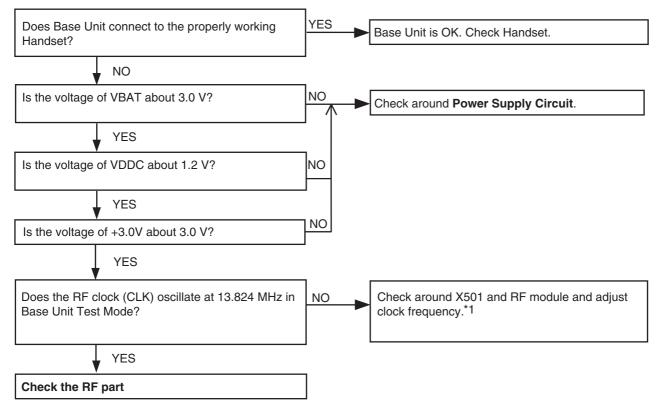
Cross Reference:
Check Power (P.33)
Charge Circuit (P.22)

10.1.5.   Check Link

10.1.5.1. Base Unit

| Does Base Unit connect to the properly working Handset? | YES → Base Unit is OK. Check Handset. |

↓ NO

| Is the voltage of VBAT about 3.0 V? | NO → Check around **Power Supply Circuit**. |

↓ YES

| Is the voltage of VDDC about 1.2 V? | NO |

↓ YES

| Is the voltage of +3.0V about 3.0 V? | NO |

↓ YES

| Does the RF clock (CLK) oscillate at 13.824 MHz in Base Unit Test Mode? | NO → Check around X501 and RF module and adjust clock frequency.*1 |

↓ YES

Check the RF part

Cross Reference:
    Power Supply Circuit/Reset Circuit (P.13)
    Check the RF part (P.40)
Note:
    Refer to **Things to Do after Replacing IC or X'tal** (P.52)(P.58) for Base Unit.
    *1 How to adjust the frequency of X501:
    To see the frequency, execute the command "SFR", then check the TP_CKM (IC501-57pin).
    To adjust frequency, send command "SFR ⊔○○⊔○○"until the frequency counter becomes13.824 MHZ±55HZ.
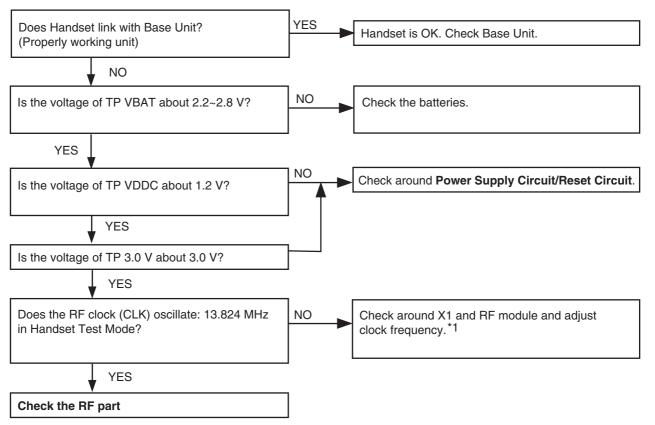
10.1.5.2. Handset

Does Handset link with Base Unit? (Properly working unit)	YES → Handset is OK. Check Base Unit.

NO ↓

Is the voltage of TP VBAT about 2.2~2.8 V?	NO → Check the batteries.

YES ↓

Is the voltage of TP VDDC about 1.2 V?	NO → Check around **Power Supply Circuit/Reset Circuit**.

YES ↓

Is the voltage of TP 3.0 V about 3.0 V?	

YES ↓

Does the RF clock (CLK) oscillate: 13.824 MHz in Handset Test Mode?	NO → Check around X1 and RF module and adjust clock frequency. *1

YES ↓

Check the RF part

Cross Reference:
> **Power Supply Circuit/Reset Circuit** (P.21)
> **Check the RF part** (P.40)

Note:
> Refer to **Things to Do after Replacing IC or X'tal** (P.53)(P.59) for Handset.
> *1 How to adjust the frequency of X1:
> To see the frequency, execute the command "SFR", then check the TP_CKM (IC1-57pin).
>
> To adjust frequency, send command "SFR ⊔○○⊔○○"until the frequency counter becomes13.824 MHz±55HZ.
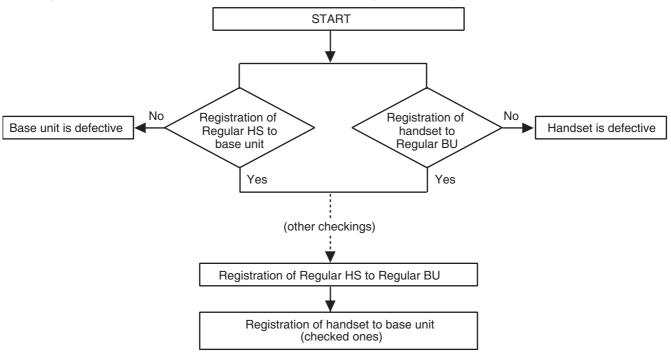
10.1.6.   Check the RF part

10.1.6.1.   Finding out the Defective part

1. Prepare Regular HS(*1) and Regular BU(*2).
2. a. Re-register regular HS (Normal mode) to base unit (to be checked).
   If this operation fails in some ways, the base unit is defective.
   b. Re-register handset (to be checked) to regular BU (Normal mode).
   If this operation fails in some ways, the handset is defective.

After All the Checkings or Repairing
1. Re-register the checked handset to the checked base unit, and Regular HS to Regular BU.

```
                          ┌─────────────────────┐
                          │        START        │
                          └─────────────────────┘
                                     │
                                     ▼
          No    ◇ Registration of ◇        ◇ Registration of ◇   No
┌──────────────┐   ◇ Regular HS to ◇        ◇ handset to      ◇  ──────►┌──────────────────┐
│Base unit is  │◄──  base unit               Regular BU              │Handset is defective│
│defective     │   ◇               ◇        ◇                 ◇       └──────────────────┘
└──────────────┘        Yes                        Yes

                          (other checkings)
                                     ▼
          ┌───────────────────────────────────────────┐
          │  Registration of Regular HS to Regular BU  │
          └───────────────────────────────────────────┘
                                     │
                                     ▼
          ┌───────────────────────────────────────────┐
          │  Registration of handset to base unit      │
          │           (checked ones)                   │
          └───────────────────────────────────────────┘
```
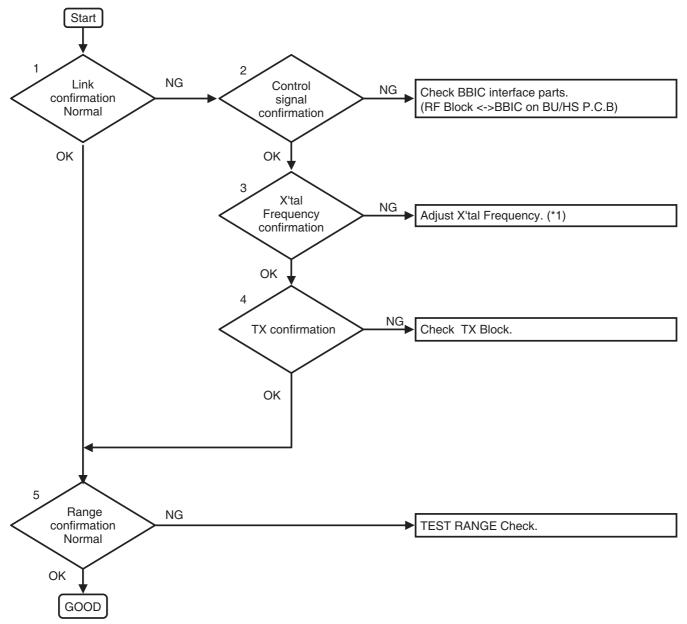
Note:
(*1) HS: Handset
(*2) BU: Base Unit

10.1.6.2. RF Check Flowchart

Each item (1 ~ 5) of RF Check Flowchart corresponds to **Check Table for RF part** (P.42).
Please refer to the each item.

```
                    ┌─────────┐
                    │  Start  │
                    └────┬────┘
                         │
                         ▼
      1 ◇Link confirmation  ──NG──►  2 ◇Control signal  ──NG──►  Check BBIC interface parts.
        Normal                        confirmation               (RF Block <->BBIC on BU/HS P.C.B)
        │                             │
       OK                            OK
        │                             ▼
        │                    3 ◇X'tal Frequency  ──NG──►  Adjust X'tal Frequency. (*1)
        │                        confirmation
        │                             │
        │                            OK
        │                             ▼
        │                    4 ◇TX confirmation  ──NG──►  Check  TX Block.
        │                             │
        │                            OK
        │                             │
        ◄─────────────────────────────┘
        │
        ▼
      5 ◇Range confirmation  ──NG──►  TEST RANGE Check.
        Normal
        │
       OK
        ▼
    ┌────────┐
    │  GOOD  │
    └────────┘
```

Note:
   (*1) Refer to **Check Link** (P.38).

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10.1.6.3. Check Table for RF part

No.	Item	BU (Base Unit) Check	HS (Handset) Check
1	Link Confirmation Normal HS, BU Mode [Normal Mode]	1. Register Regular HS to BU (to be checked). 2. Press [Talk] key of the Regular HS to establish link.	1. Register HS (to be checked) to Regular BU. 2. Press [Talk] key of the HS to establish link.
2	X'tal Frequency confirmation HS, BU Mode: [Adjustment]	Check X'tal Frequency. (13.824000 MHz ±100 Hz)	Check X'tal Frequency. (13.824000 MHz ±100 Hz)
3	TX confirmation HS Mode: [HS_Burst Mode] (*1) BS Mode: [BS_Burst Mode] (*2)	1. Remove wire antenna 2 and connect spectrum analyzer to TP. (*3) 2. Confirm TX power whether spec. is satisfied. Power >=14.5dBm	1. Connect spectrum analyzer to TP.(*4) 2. Confirm TX power whether satisfied spec. Power >=16.0dBm
4	Range Confirmation Normal HS, BU Mode: [Normal Mode]	1. Register Regular HS to BU (to be checked). 2. Press [Talk] key of the Regular HS to establish link. 3. Compare the range of the BU (being checked) with that of the Regular BU.	1. Register HS (to be checked) to Regular BU. 2. Press [Talk] key of the HS to establish link. 3. Compare the range of the HS (being checked) with that of the Regular HS.

Note:

(*1) Refer to **Commands (Handset)** (P.55)

(*2) Refer to **Commands (Base Unit)** (P.55)

(*3) **Adjustment Standard (Base Unit)** (P.56)

(*4) **Adjustment Standard (Handset)** (P.57)

10.1.6.4. TEST RANGE Check

Circuit block which range is defective can be found by the following check.

Item	BU (Base Unit) Check	HS (Handset) Check
Range Confirmation TX TEST (TX Power check) HS, BU setting Checked unit: Low TX power (*1) Regular unit: High TX power (*1)	1. Register Regular HS to BU (to be checked). 2. Set TX Power of the BU and the Regular HS according to CHART1. 3. At distance of about 20m between HS and BU, Link OK = TX Power of the BU is OK. No Link = TX Power of the BU is NG.	1. Register HS (to be checked) to Regular BU. 2. Set TX Power of the HS and the Regular BU according to CHART1. 3. At distance of about 20m between HS and BU, Link OK = TX Power of the HS is OK. No Link = TX Power of the HS is NG.
Range Confirmation RX TEST (RX sensitivity check) HS, BU setting Checked unit: High TX power (*1) Regular unit: Low TX power (*1)	1. Register Regular HS to BU (to be checked). 2. Set TX Power of the BU and the Regular HS according to CHART1. 3. At distance of about 20m between HS and BU, Link OK= RX Sensitivity of the BU is OK. No Link = RX Sensitivity of the BU is NG.	1. Register HS (to be checked) to Regular BU. 2. Set TX Power of the Checking HS and the Regular BU according to CHART1. 3. At distance of about 20m between HS and BU, Link OK= RX Sensitivity of the HS is OK. No Link = RX Sensitivity of the HS is NG

CHART1: Setting of TX Power and RX Sensitivity in Range Confirmation TX TEST, RX TEST

	BU (to be checked)	Regular_HS
	TX Power	TX Power
BU (Base Unit) TX Power Check	Low	High
BU (Base Unit) RX Sensitivity Check	High	**Low**

	HS (to be checked)	Regular_BU
	TX Power	TX Power
HS (Handset) TX Power Check	Low	High
HS (Handset) RX Sensitivity Check	High	**Low**

Note:

(*1) Refer to **Commands (Base Unit)** (P.55).

10.1.7. Registering a Handset to the Base Unit

The supplied handset and base unit are pre-registered. If for some reason the handset is not registered to the base unit, re-register the handset.

1 Handset:
   【MENU】 ⟶ # 1 3 0
2 Base unit:
   Press and hold 【LOCATOR】 for about 5 seconds until the registration tone sounds.
   ● If all registered handsets start ringing, press 【LOCATOR】 again to stop, then repeat this step.
   ● The next step must be completed within 90 seconds.
3 Handset:
   Press 【OK】, then wait until a long beep sounds.

Note:
● While registering, "registering handset" is displayed on all registered handsets.
● When you purchase an additional handset, refer to the additional handset's installation manual for registration.
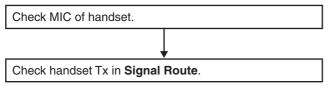
10.1.8. Deregistering a Handset

A handset can cancel its own registration to the base unit, or other handsets registered to the same base unit. This allows the handset to end its wireless connection with the system.

1 【MENU】 ⟶ # 1 3 1
   ● All handsets registered to the base unit are displayed.
2 【⬍】: Select the handset you want to cancel. ⟶ 【SELECT】
3 【⬍】: "Yes" ⟶ 【SELECT】
4 【OFF】

10.1.9. Check Handset Transmission

| Check MIC of handset. |

↓

| Check handset Tx in **Signal Route**. |
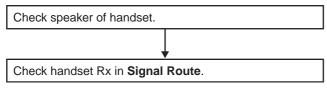
Cross Reference:
   Signal Route (P.24)

10.1.10. Check Handset Reception

| Check speaker of handset. |

↓

| Check handset Rx in **Signal Route**. |
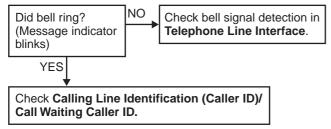
Cross Reference:
   Signal Route (P.24)
Note:
   When checking the RF part, Refer to **Check the RF part** (P.40).

10.1.11. Check Caller ID

BASE UNIT

| Did bell ring? (Message indicator blinks) | —NO→ | Check bell signal detection in **Telephone Line Interface**. |

YES ↓

| Check **Calling Line Identification (Caller ID)/ Call Waiting Caller ID.** |

Cross Reference:
   Telephone Line Interface (P.15)
   Calling Line Identification (Caller ID)/Call Waiting Caller ID (P.17)
Note:
 • Make sure the format of the Caller ID service of the Telephone company that the customer subscribes to.
 • It is also recommended to confirm that the customer is really a subscriber of the service.
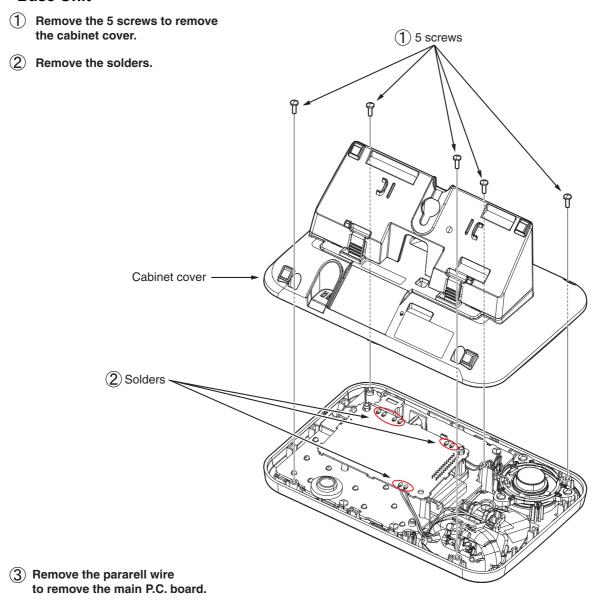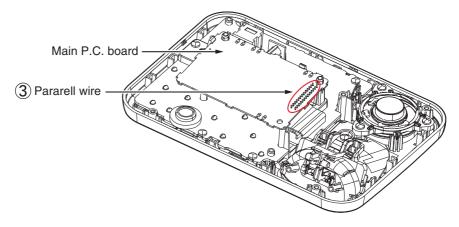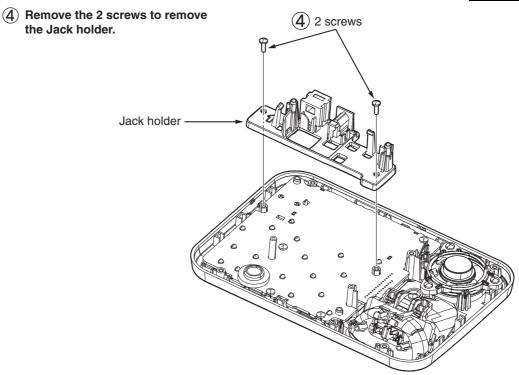
11 Disassembly and Assembly Instructions
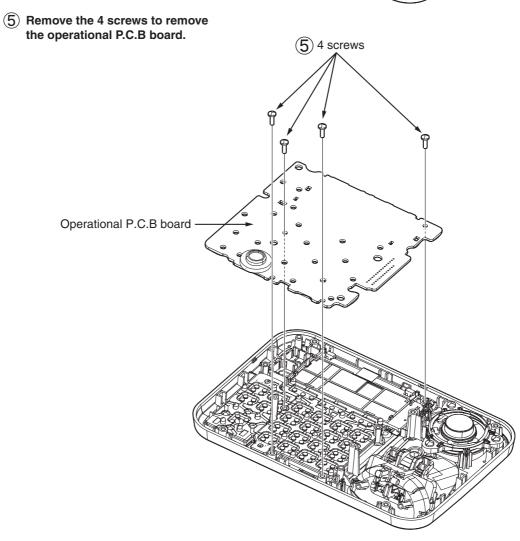
11.1. Disassembly Instructions

11.1.1. Base Unit

① **Remove the 5 screws to remove the cabinet cover.**

② **Remove the solders.**

① 5 screws

Cabinet cover

② Solders

③ **Remove the pararell wire to remove the main P.C. board.**

Main P.C. board

③ Pararell wire

④ **Remove the 2 screws to remove the Jack holder.**

④ 2 screws

Jack holder

⑤ **Remove the 4 screws to remove the operational P.C.B board.**

⑤ 4 screws

Operational P.C.B board
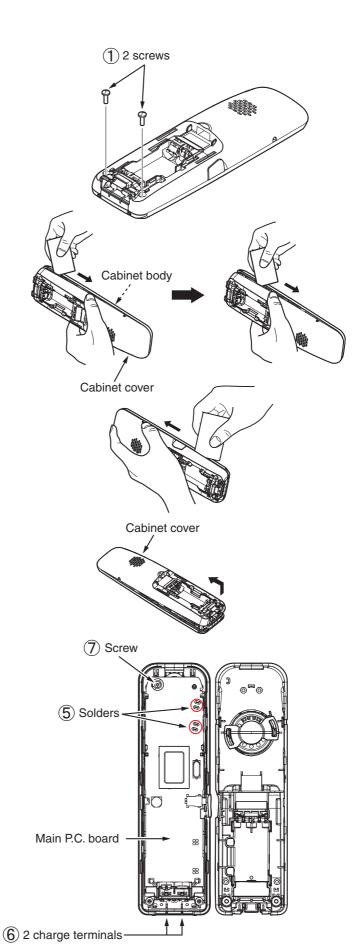
11.1.2. Handset

① **Remove the 2 screws.**

① 2 screws
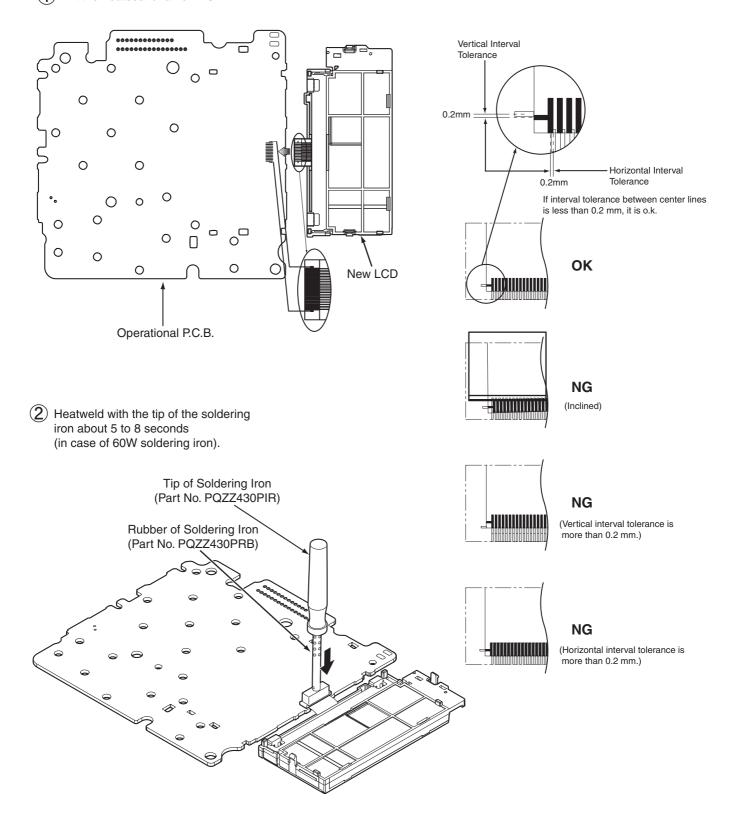
② **Insert a JIG (PQDJ10006Y) between the cabinet body and the cabinet cover, then pull it along the gap to open the cabinet.**

Cabinet body

Cabinet cover

③ **Likewise, open the other side of the cabinet.**

④ **Remove the cabinet cover by pushing it upward.**

Cabinet cover

⑦ Screw

⑤ **Remove the solders.**

⑤ Solders

⑥ **Remove the solders to remove the 2 charge terminals.**

Main P.C. board

⑦ **Remove the screw to remove the main P. C. board.**

⑥ 2 charge terminals
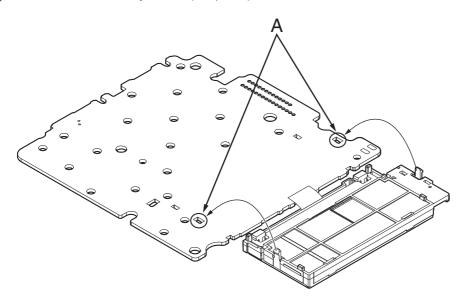
11.2. How to Replace the Base Unit LCD

① Fit the heatseal of a new LCD.

Operational P.C.B.

New LCD

Vertical Interval Tolerance

0.2mm

Horizontal Interval Tolerance

0.2mm

If interval tolerance between center lines is less than 0.2 mm, it is o.k.

OK

NG

(Inclined)

NG

(Vertical interval tolerance is more than 0.2 mm.)

NG

(Horizontal interval tolerance is more than 0.2 mm.)

② Heatweld with the tip of the soldering iron about 5 to 8 seconds
(in case of 60W soldering iron).

Tip of Soldering Iron
(Part No. PQZZ430PIR)

Rubber of Soldering Iron
(Part No. PQZZ430PRB)

③ Attach the LCD and fix by hook A (two points).

A

④ Solder the wires.

A

11.3. How to Replace the Handset LCD

Note:
The illustrations are simplified in this page.
They may differ from the actual product.
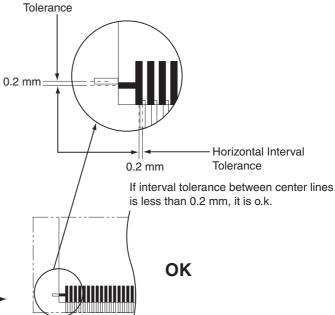
①

P. C. board
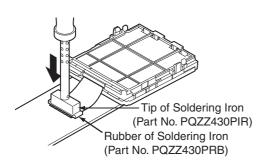
Peel off the FFC (Flexible Flat Cable) from
the LCD, in the direction of the arrow. Take
care to ensure that the foil on the P.C. board
is not damaged.
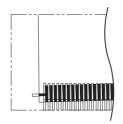
②

New LCD

Fit the heatseal of a new LCD.
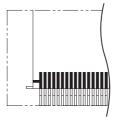
Vertical Interval
Tolerance

0.2 mm

0.2 mm

Horizontal Interval
Tolerance

If interval tolerance between center lines
is less than 0.2 mm, it is o.k.

OK

③

Tip of Soldering Iron
(Part No. PQZZ430PIR)
Rubber of Soldering Iron
(Part No. PQZZ430PRB)

Heatweld with the tip of the soldering
iron about 5 to 8 seconds
(in case of 60W soldering iron).

NG
(Inclined)

NG
(Vertical interval tolerance is
more than 0.2 mm.)

NG
(Horizontal interval tolerance is
more than 0.2 mm.)

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12 Measurements and Adjustments

This chapter explains the measuring equipment, the JIG connection, and the PC setting method necessary for the measurement in **Troubleshooting Guide** (P.32)

12.1. Equipment Required

- Digital multi-meter (DMM): it must be able to measure voltage and current.
- Oscilloscope.
- Frequency counter: It must be precise enough to measure intervals of 1 Hz (precision; ±4 ppm)
  Hewlett Packard, 53131A is recommended.
- DECT tester: Rohde & Schwarz, CMD 60 is recommended.
  This equipment may be useful in order to precisely adjust like a mass production.

12.2. The Setting Method of JIG

<Preparation>
- Serial JIG cable: PQZZ1CD300E*
- PC which runs in DOS mode
- **Batch file CD-ROM** for setting: PNZZTG6841BX
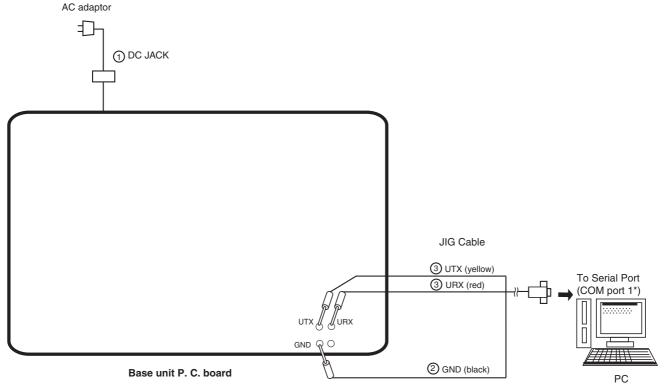
Note:
*: If you have the JIG Cable for TCD500 series (PQZZ1CD505E), change the following values of resistance. Then you can use it as a JIG Cable for both TCD300 and TCD500 series. (It is an upper compatible JIG Cable.)

Resistor	Old value (kΩ)	New value (kΩ)
R2	22	3.3
R3	22	3.3
R4	22	4.7
R7	4.7	10

12.2.1. Connections (Base Unit)

① Connect the AC adaptor.
② Connect the JIG Cable GND (black).
③ Connect the JIG Cable RX (red) and TX (yellow).
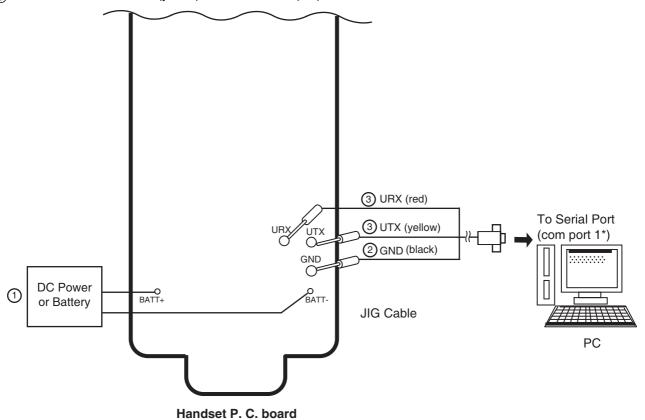
Note:
*: COM port names may vary depending on what your PC calls it.

12.2.2. Connections (Handset)

①Connect the DC Power or Battery to BATT+ and BATT-.

②Connect the JIG cable GND (black) to GND.

③Connect the JIG cable UTX (yellow) to UTX and URX (red) to URX.

Handset P. C. board

Note:

*: COM port names may vary depending on what your PC calls it.

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12.2.3. How to install Batch file into P.C.

1. Insert the Batch file CD-ROM into CD-ROM drive and
copy PNZZTG**** folder to your PC (example: D drive).

<Example for Windows>

2. Open an MS-DOS mode window.

On your computer, click **[Start]**, select **Programs**
(**All Programs** for Windows XP/Windows Server 2003),
then click
MS-DOS Prompt. (for Windows 95/Windows 98)
Or
Accessories-MS-DOS Prompt. (for Windows Me)
Or
Command Prompt. (for Windows NT 4.0)
Or
Accessories-Command Prompt.
(for Windows 2000/Windows XP/Windows Server 2003)

3. At the DOS prompt, type "**D:**" (for example) to select the
drive, then press the **Enter** key.

4. Type "**CD ¥PNZZTG****", then press the **Enter** key.

<Example>

```
C: ¥Documents and Settings>D:
D: ¥>CD ¥PNZZTG****
D: ¥PNZZTG**** >SET_COM=X
D: ¥PNZZTG****>READID
00 52 4F A8 A8
D: ¥PNZZTG****>DOSKEY
D: ¥PNZZTG****>▄
```

5. Type "**SET_COM=X**", then press the **Enter** key
(**X**: COM port number used for the serial connection on your PC).

6. Type "**READID**", then press the **Enter** key.
  ·If any error messages appear, change the port number or
   check the cable connection.
  ·If any value appear, go to next step.

<Example: error happens>

```
C: ¥Documents and Settings>D:
D: ¥>CD ¥PNZZTG****
D: ¥PNZZTG**** >SET_COM=X
D: ¥PNZZTG****>READID
   CreateFile error
ERROR 10: Can't open serial port
D: ¥PNZZTG ****>▄
```

7. Type "**DOSKEY**", then press the **Enter** key.

Note:
• "*****" varies depending on the country or models.

12.2.4. Commands (Base Unit)

See the table below for frequently used commands.

Command name		Function	Example
rdeeprom		Read the data of EEPROM	Type "rdeeprom 00 00 FF", and the data from address "00 00" to "FF" is read out.
readid		Read ID (RFPI)	Type "readid", and the registered ID is read out.
writeid		Write ID (RFPI)	Type "writeid 00 18 E0 0E 98", and the ID "0018 E0 0E 98" is written.
hookoff		Off-hook mode on Base	Type "hookoff".
hookon		On-hook mode on Base	Type "hookon".
getchk		Read checksum	Type "getchk".
How to use of "getchk"	1.rdeeprom	Read EEPROM	Type "RdEeprom 03 F2 04", and the data from address "03 F2" to "03 F5" is read out *This command gets 4 byte "WW", "XX", "YY", "ZZ". *Please NEVER forget these 4 byte data!
	2.sendchar epw	Write EEPROM	Type "sendchar epw 03 F2 04 FF FF FF FF"
	3.sendchar RST	Reset baseset	Type "sendchar RST"
	4.getchk	Read checksum	Type "getchk".
	5.sendchar epw	Write EEPROM	Type "sendchar epw 03 F2 04 WW XX YY ZZ" *"WW", "XX", "YY", "ZZ" is 4 byte data that already read from same address.
wreeprom		Write the data of EEPROM	Type "wreeprom 01 23 45". "01 23" is address and "45" is data to be written.

12.2.5. Commands (Handset)
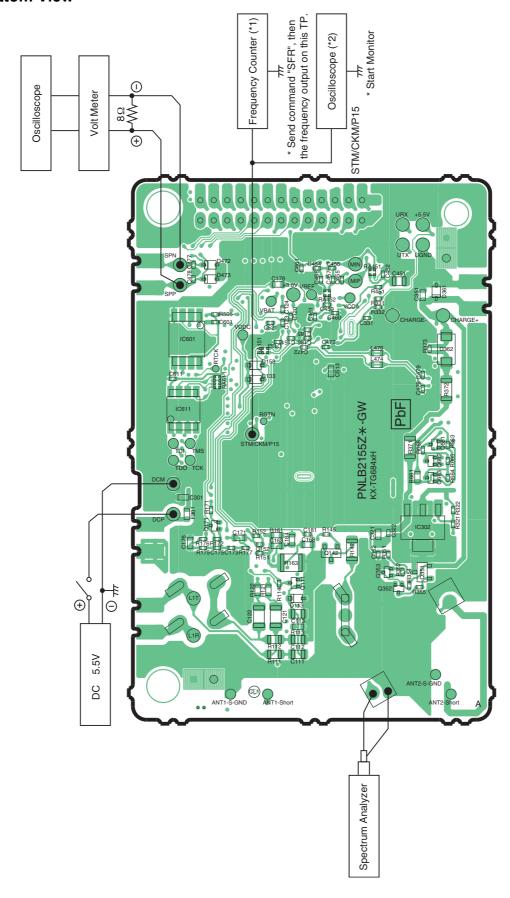
See the table below for frequently used commands.

Command name		Function	Example
rdeeprom		Read the data of EEPROM	Type "rdeeprom 00 00 FF", and the data from address "00 00" to "FF" is read out.
readid		Read ID (RFPI)	Type "readid", and the registered ID is read out.
writeid		Write ID (RFPI)	Type "writeid 00 18 E0 0E 98", and the ID "0018 E0 0E 98" is written.
getchk		Read checksum	Type "getchk"
How to use of "getchk"	1.rdeeprom	Read EEPROM	Type "RdEeprom 03 7D 04", and the data from address "03 7D" to "03 80" is read out *NEVER forget the read 4 byte data!
	2.sendchar epw	Write EEPROM	Type "sendchar epw 03 7D 04 FF FF FF FF"
	3.sendchar RST	Reset baseset	Type "sendchar RST"
	4.getchk	Read checksum	Type "getchk".
	5.sendchar epw	Write EEPROM	Type "sendchar epw 03 7D 04 WW XX YY ZZ" *"WW", "XX", "YY", "ZZ" is 4 byte data that already read from same address.
weeprom		Write the data of EEPROM	Type"wreeprom 01 23 45". "01 23" is address and "45" is data to be written.

12.3. Adjustment Standard (Base Unit)

When connecting the simulator equipment for checking, please refer to below.

12.3.1. Bottom View
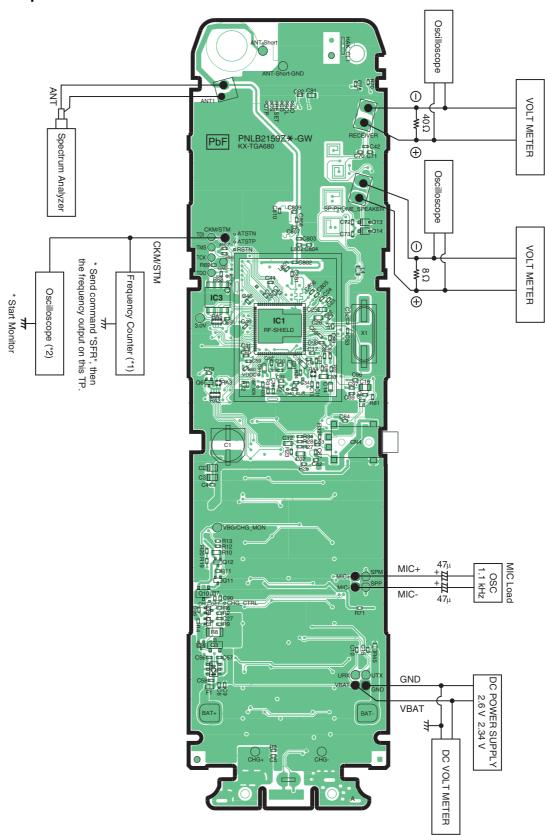
Note:

(*1) refers to No.2 of Check **Check Table for RF part** (P.42)

(*2) refers to **Power Supply Circuit/Reset Circuit** (P.13)

12.4. Adjustment Standard (Handset)

When connecting the simulator equipment for checking, please refer to below.

12.4.1. Component View

Note:
(*1) refers to No.2 of Check **Check Table for RF part** (P.42)
(*2) refers to **Power Supply Circuit/Reset Circuit** (P.21)

12.5. Things to Do after Replacing IC or X'tal

If repairing or replacing EEPROM and X'tal, it is necessary to download the required data such as Programming data or adjustment data, etc in memory.

The set doesn't operate if it is not executed.

12.5.1. How to download the data

12.5.1.1. Base Unit

First, operate the PC setting according to **The Setting Method of JIG** (P.52).

Then download the appropriate data according to the following procedures.

	Items	How to download/Required adjustment
EEPROM (IC611)	Adjusted parameter data is stored in memory. (country version batch file, default batch file, etc.)	1) Change the address "0001" of EEPROM to "AA" to download the data. 2) Default batch file: Execute the command "default.bat". 3) Country version batch file: Execute the command "TG6841US_WW_RevXXX_YYY.bat". (*1) 4) Clock adjustment
X'tal (X1)	System clock	Clock adjustment data is in EEPROM, adjust the data again after replacing it. 1) Apply 5.5V between DCP ad DCM with DC power. 2) Input Command "sendchar sfr", then you can confirm the current value. 3) Check X'tal Frequency.(13.824 MHz ± 100 Hz). 4) If the frequency is not 13.824 MHz ± 100 Hz, adjust the frequency of CLK executing the command "sendchar sfr xx xx (where xx is the value)" so that the reading of the frequency counter is 13.824000 MHz ± 15 Hz.

Note:

(*1) WW: country code, XXX_YYY: revision number

"XXX", "YYY" vary depending on the country version. You can find them in the batch file, PNZZ- mentioned in **The Setting Method of JIG** (P.52).

12.5.1.2. Handset

First, operate the PC setting according to **The Setting Method of JIG** (P.52).

Then download the appropriate data according to the following procedures.

Items		How to download/Required adjustment
EEPROM (IC3)	Adjusted parameter data is stored in memory. (country version batch file, default batch file, etc.)	1) Default batch file: Execute the command "default.bat". 2) Default batch file (remaining): Execute the command "TGA680US_DEF_RevXXX_YYY.bat". (*2) 3) Country version batch file: Execute the command "TGA680US_WW_RevXXX_YYY.bat". (*2) 4) Clock adjustment 5) 2.35 V setting and battery low detection
X'tal (X1)	System clock	1) Apply 2.6V between BATT+ and BATT- with DC power. 2) Input Command "sendchar sfr", then you can confirm the current value. 3) Check X'tal Frequency.(13.824 MHz ± 100 Hz). 4) If the frequency is not 13.824 MHz ± 100 Hz, adjust the frequency of CLK executing the command "sendchar sfr xx xx (where xx is the value)" so that the reading of the frequency counter is 13.824000 MHz ± 5 Hz.

Note:

(*2) WW: country code, XXX_YYY: revision number

"XXX" and "YYY" vary depending on the country version. You can find them in the batch file, PNZZ- mentioned in **The Setting Method of JIG** (P.52).

12.6. Frequency Table

	Ch. (hex)	TX/RX Frequency (MHz)
Channel 0	00	1928.448
Channel 1	01	1926.720
Channel 2	02	1924.992
Channel 3	03	1923.264
Channel 4	04	1921.536

13 Miscellaneous

13.1. How to Replace the LLP (Leadless Leadframe Package) IC

Note:
    This description only applies to the model with Shield case.

13.1.1. Preparation

 • PbF (: Pb free) Solder
 • Soldering Iron
   Tip Temperature of 700 °F ± 20 °F (370 °C ± 10 °C)
   Note:
   We recommend a 30 to 40 Watt soldering iron. An expert may be able to use a 60 to 80 Watt iron where someone with less
   experience could overheat and damage the PCB foil.
 • Hot Air Desoldering Tool
   Temperature: 608 °F ± 68 °F (320 °C ± 20 °C)

13.1.2. Caution

 • To replace the IC efficiently, choose the right sized nozzle of the hot air desoldering tool that matches the IC package.
 • Be careful about the temperature of the hot air desoldering tool not to damage the PCB and/or IC.

13.1.3. How to Remove the IC
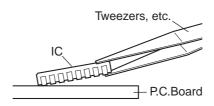
    1. Heat the IC with a hot air desoldering tool through the P.C.Board.
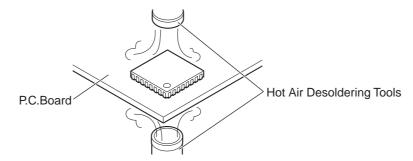
    2. Pick up the IC with tweezers, etc. when the solder is melted completely.
       Note:
       • Be careful not to touch the peripheral parts with tweezers, etc. They are unstable.
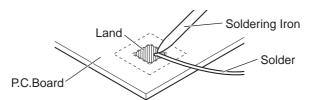
       When it is hard to melt the solder completely, heat it with a hot air desoldering tool through the IC besides through the
       P.C.Board.
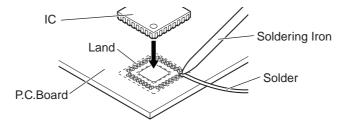
    3. After removing the IC, clean the P.C.Board of residual solder.

13.1.4. How to Install the IC
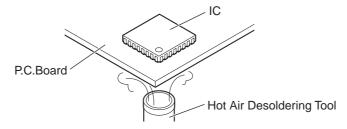
1. Place the solder a little on the land where the radiation GND pad on IC bottom is to be attached.

2. Place the solder a little on the land where IC pins are to be attached, then place the IC.
   Note:
   • When placing the IC, the positioning should be done very carefully.

3. Heat the IC with a hot air desoldering tool through the P.C.Board until the solder on IC bottom is melted.
   Note:
   • Be sure to place it precisely, controlling the air volume of the hot air desoldering tool.

4. After soldering, confirm there are no short and open circuits with visual inspection.

13.2. How to Replace the Flat Package IC

Even if you do not have the special tools (for example, a spot heater) to remove the Flat IC, with some solder (large amount), a soldering iron and a cutter knife, you can easily remove the ICs that have more than 100 pins.

13.2.1. Preparation

• PbF (: Pb free) Solder

• Soldering Iron

Tip Temperature of 700 °F ± 20 °F (370 °C ± 10 °C)

Note: We recommend a 30 to 40 Watt soldering iron. An expert may be able to use a 60 to 80 Watt iron where someone with less experience could overheat and damage the PCB foil.
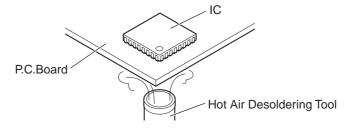
• Flux

Recommended Flux: Specific Gravity → 0.82.

Type → RMA (lower residue, non-cleaning type)
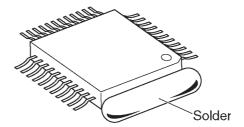
Note: See **About Lead Free Solder (Pbf: Pb free)** (P.5)

13.2.2. How to Remove the IC
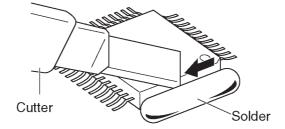
1. Put plenty of solder on the IC pins so that the pins can be completely covered.

   Note:
   If the IC pins are not soldered enough, you may give pressure to the P.C. board when cutting the pins with a cutter.
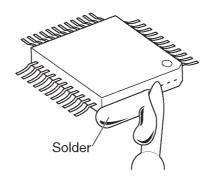
Solder

2. Make a few cuts into the joint (between the IC and its pins) first and then cut off the pins thoroughly.

Cutter   Solder

3. While the solder melts, remove it together with the IC pins.

Solder

When you attach a new IC to the board, remove all solder left on the board with some tools like a soldering wire. If some solder is left at the joint on the board, the new IC will not be attached properly.
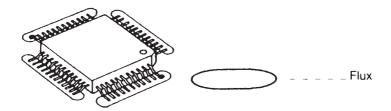
13.2.3. How to Install the IC

1. Temporarily fix the FLAT PACKAGE IC, soldering the two marked pins.

● – – – – – –Temporary soldering point.
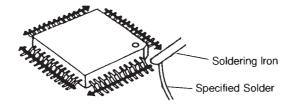
*Check the accuracy of the IC setting with the corresponding soldering foil.

2. Apply flux to all pins of the FLAT PACKAGE IC.

– – – – –Flux
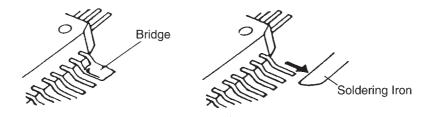
3. Solder the pins, sliding the soldering iron in the direction of the arrow.

Soldering Iron

Specified Solder
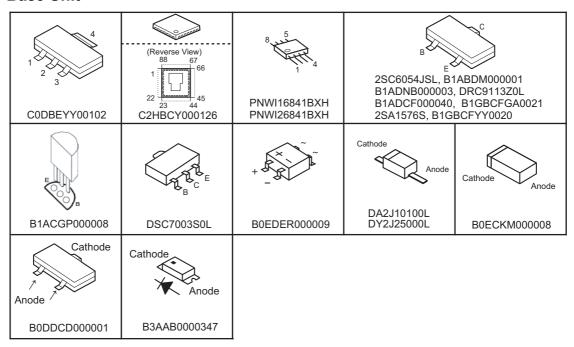
13.2.4. How to Remove a Solder Bridge

1. Lightly resolder the bridged portion.
2. Remove the remaining solder along the pins using a soldering iron as shown in the figure below.

Bridge

Soldering Iron
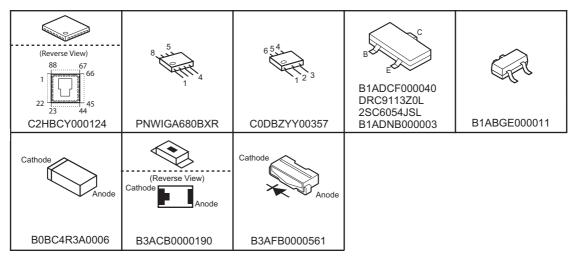
13.3. Terminal Guide of the ICs, Transistors and Diodes

13.3.1. Base Unit

C0DBEYY00102	(Reverse View) 88 67 1 66 22 45 23 44 C2HBCY000126	PNWI16841BXH PNWI26841BXH	2SC6054JSL, B1ABDM000001 B1ADNB000003, DRC9113Z0L B1ADCF000040, B1GBCFGA0021 2SA1576S, B1GBCFYY0020
B1ACGP000008	DSC7003S0L	B0EDER000009	DA2J10100L DY2J25000L / B0ECKM000008
B0DDCD000001	B3AAB0000347		

13.3.2. Handset

(Reverse View) 88 67 1 66 22 45 23 44 C2HBCY000124	PNWIGA680BXR	C0DBZYY00357	B1ADCF000040 DRC9113Z0L 2SC6054JSL B1ADNB000003	B1ABGE000011
B0BC4R3A0006	B3ACB0000190	B3AFB0000561		

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Memo

14 Schematic Diagram

14.1. For Schematic Diagram

14.1.1. Base Unit (Schematic Diagram (Base Unit_Main))

Notes:
1. DC voltage measurements are taken with voltmeter from the negative voltage line.

> Important Safety Notice:
> Components identified by ⚠ mark have special characteristics important for safety. When replacing any of these components, use only the manufacture's specified parts.

2. The schematic diagrams may be modified at any time with the development of new technology.
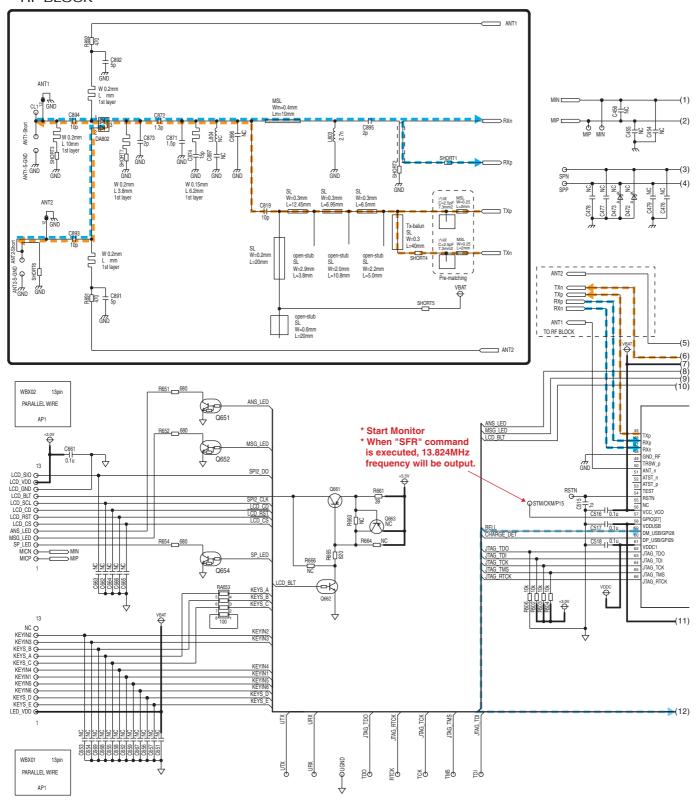
14.1.2. Handset (Schematic Diagram (Handset_Main))

Notes:
1. DC voltage measurements are taken with an oscilloscope or a tester with a ground.
2. The schematic diagrams may be modified at any time with the development of new technology.
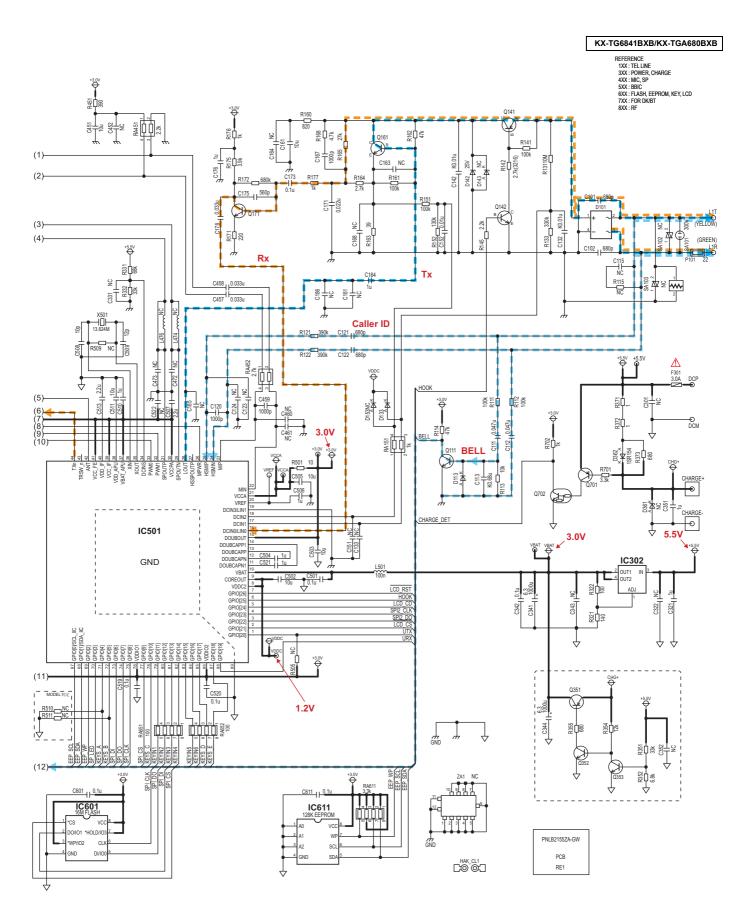
14.2. Schematic Diagram (Base Unit_Main)

RF BLOCK

* Start Monitor
* When "SFR" command is executed, 13.824MHz frequency will be output.

NC: No Components

REFERENCE
1XX : TEL LINE
3XX : POWER, CHARGE
4XX : MIC, SP
5XX : BBIC
6XX : FLASH, EEPROM, KEY, LCD
7XX : FOR DK/BT
8XX : RF
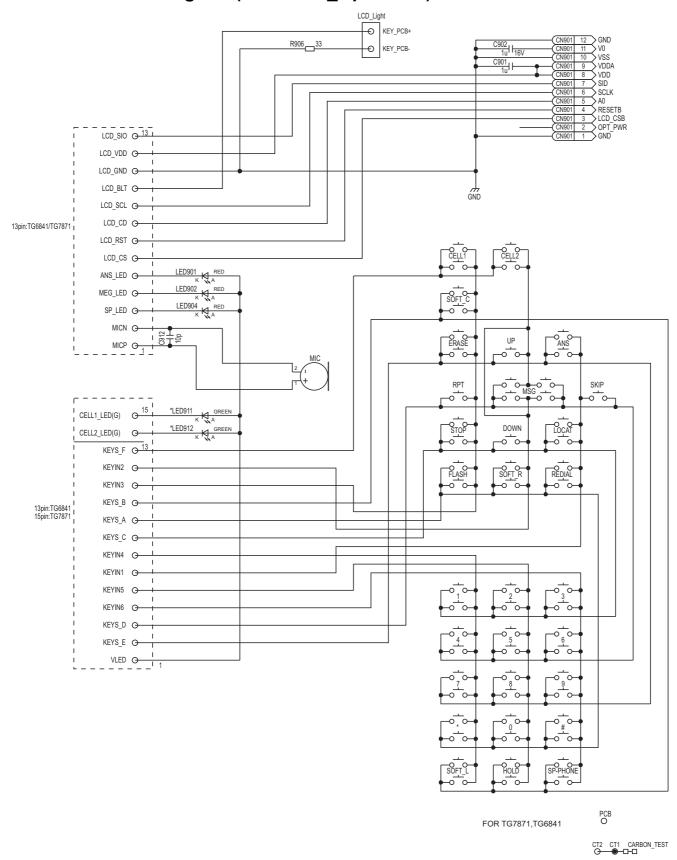
NC: No Components
KX-TG6841BX SCHEMATIC DIAGRAM (Base Unit_Main)

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14.3. Schematic Diagram (Base Unit_Operation)

NC: No Components

KX-TG6841 SCHEMATIC DIAGRAM (Base Unit_Operation)

Memo

14.4. Schematic Diagram (Base Unit_LED)

LED

+

−

KX-TG6841 SCHEMATIC DIAGRAM (Base Unit_LED)
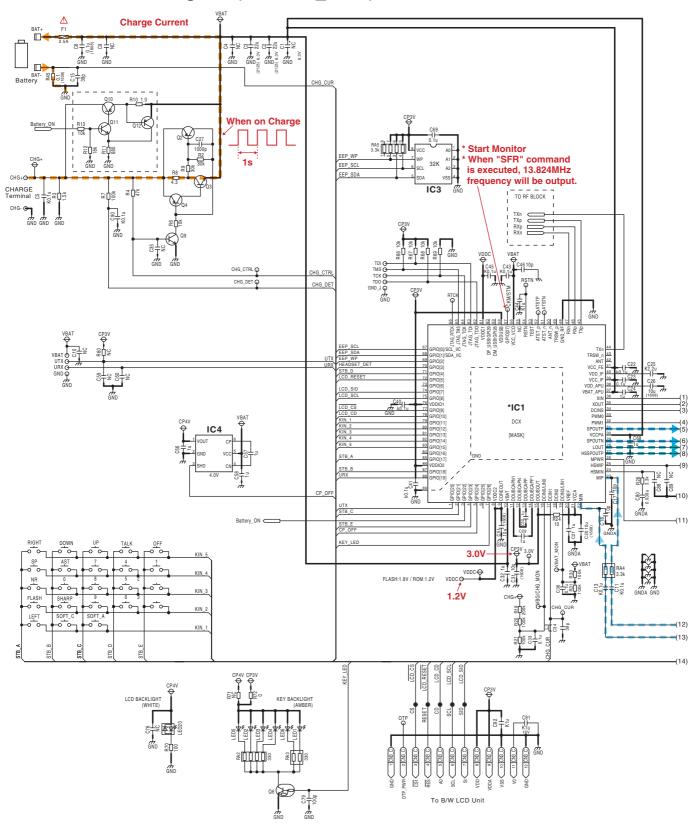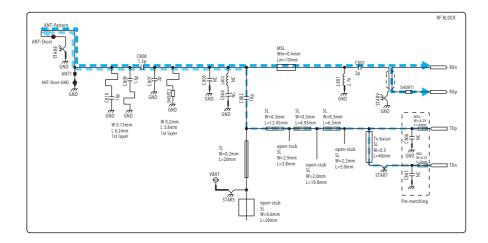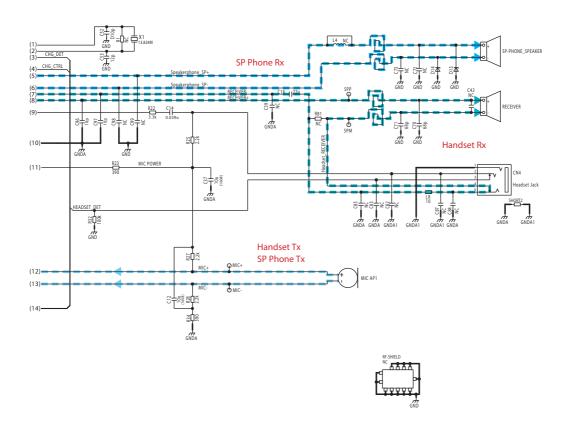
Memo

14.5. Schematic Diagram (Handset_Main)

NC: No Components

RF BLOCK

ANT-Pattern
ANT-Short
STAR8
GND
ANT1
ANT-Short-GND
GND

C808
1.3p

C810
15p

C809
1.5p

C807
4p

SHORT3
GND

C803
NC

C804
NC

L802
NC

C802
10p

W 0.15mm
L 6.2mm
1st layer

W 0.2mm
L 3.8mm
1st layer

MSL
Wm=0.4mm
Lm=10mm

C801
2p

L801
2.7n

SHORT1

STAR9
GND

RXn

RXp

SL
W=0.2mm
L=20mm

VBAT

STAR5

open-stub
SL
W=0.6mm
L=20mm

SL
W=0.3mm
L=12.45mm

SL
W=0.3mm
L=6.95mm

SL
W=0.3mm
L=6.5mm

open-stub
SL
W=2.9mm
L=3.8mm

open-stub
SL
W=2.0mm
L=10.8mm

open-stub
SL
W=2.2mm
L=5.0mm

Tx-balun
SL
W=0.3
L=40mm

STAR7

C806
NC

MSL
W=0.25
L=2mm

GND

C806
NC

MSL
W=0.25
L=2mm

C805
NC

Pre-matching

TXp

TXn

---

(1)
(2)
(3)
CHG_DET
(4)
CHG_CTRL
(5)
(6)
(7)
(8)
(9)

(10)

(11)

(12)
(13)

(14)

C52
D10p
GND

R_
NC

X1
13.824M

C53
12p
GND

Speakerphone_SP+

Speakerphone_SP-

RECEIVER-
RECEIVER+

C16
22u

C39
NC
GNDA

C96
10p

C97
10p

C98
NC

C99
NC

R22
3.3k

C14
0.039u

R25
22k

R23
390

MIC POWER

C37
10u
(1608)
GNDA

HEADSET_DET

R32
100k
GND

R27
22k

MIC+

C12
10u
(1608)

R28
22k

R34
390
GNDA

MIC+

MIC-

SP Phone Rx

L4   NC

C73
NC
GND

C72
NC
GND

D14
GND

D13
GND

SP-PHONE_SPEAKER

C42
NC

SPP

R81
NC

SPM

C71
68p
GND

C70
68p
GND

RECEIVER

Handset Rx

Handset_RECEIVER

CN4
Headset Jack

C35
NC
GNDA

C33
NC
GNDA

C32
NC
GNDA1

L8
10
GNDA1

C87
NC
GNDA1

C84
NC
GNDA

SHORT2
GNDA   GNDA1

Handset Tx
SP Phone Tx

MIC+

MIC-

MIC AP1

RF-SHIELD
NC

GND

NC: No Components
KX-TGA680BX SCHEMATIC DIAGRAM (Handset_Main)
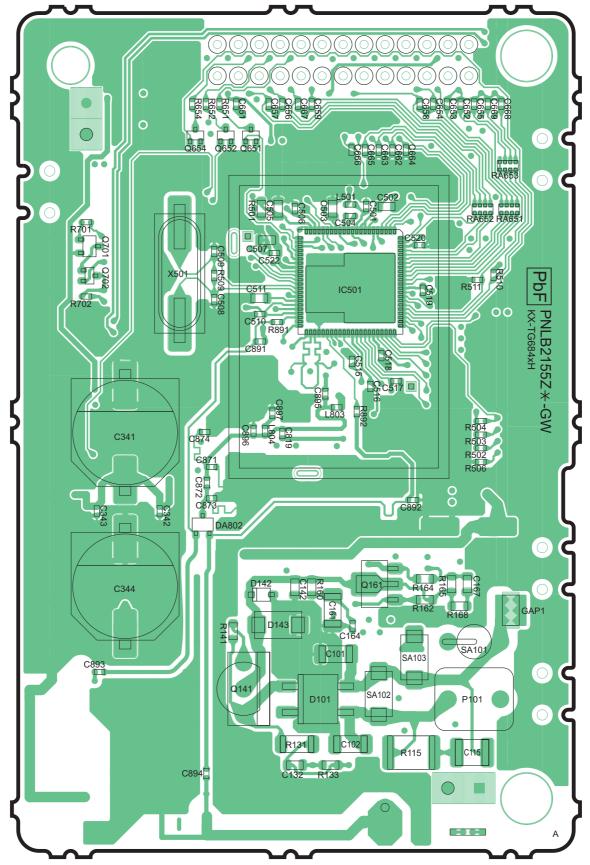
Memo

15 Printed Circuit Board
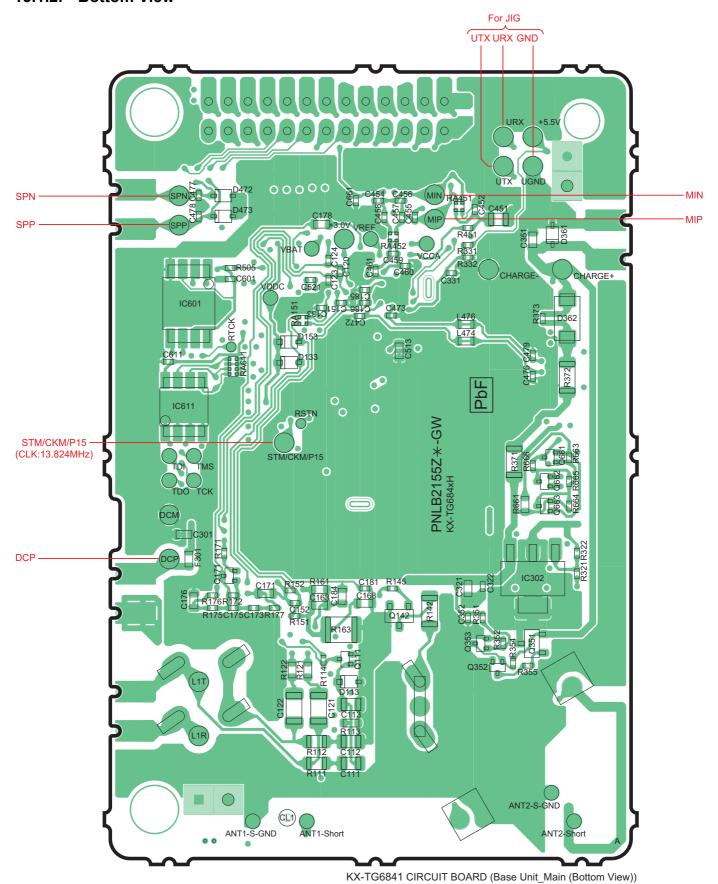
15.1. Circuit Board (Base Unit_Main)

15.1.1. Component View
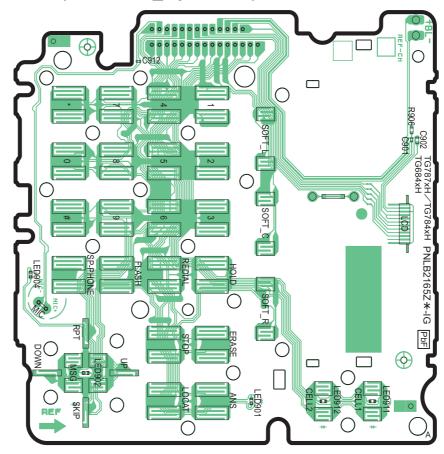
KX-TG6841 CIRCUIT BOARD (Base Unit_Main (Component View))

15.1.2. Bottom View

KX-TG6841 CIRCUIT BOARD (Base Unit_Main (Bottom View))

15.2. Circuit Board (Base Unit_Operation)

KX-TG6841 CIRCUIT BOARD (Base Unit_Operation (Component View))

15.3. Circuit Board (Base Unit_LED)
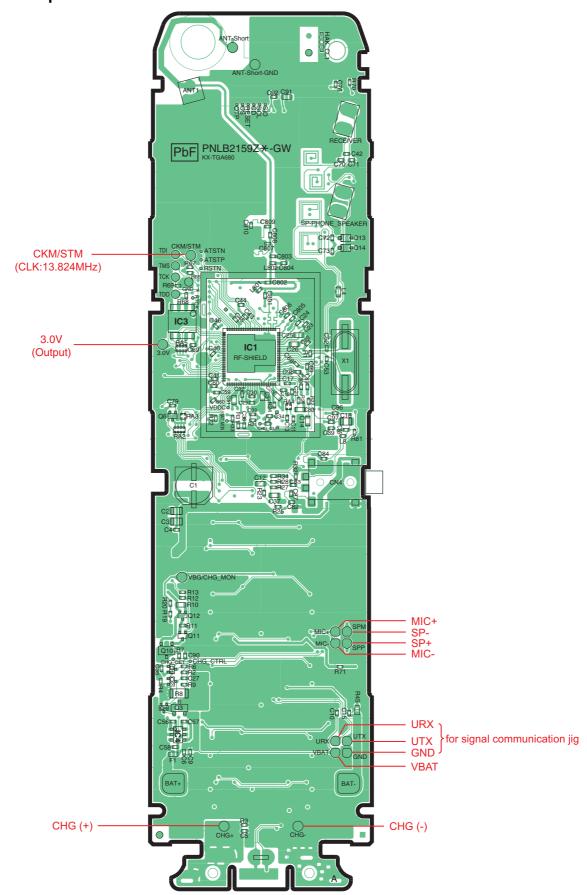
KX-TG6841 CIRCUIT BOARD (Base Unit_LED (Component View))

Memo
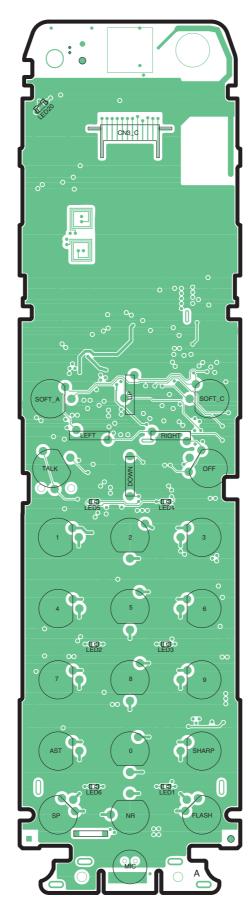
15.4. Circuit Board (Handset_Main)

15.4.1. Component View

CKM/STM (CLK:13.824MHz)

3.0V (Output)

MIC+
SP-
SP+
MIC-

URX
UTX } for signal communication jig
GND
VBAT

CHG (+)
CHG (-)

KX-TGA680 CIRCUIT BOARD (Handset_Main (Component View))
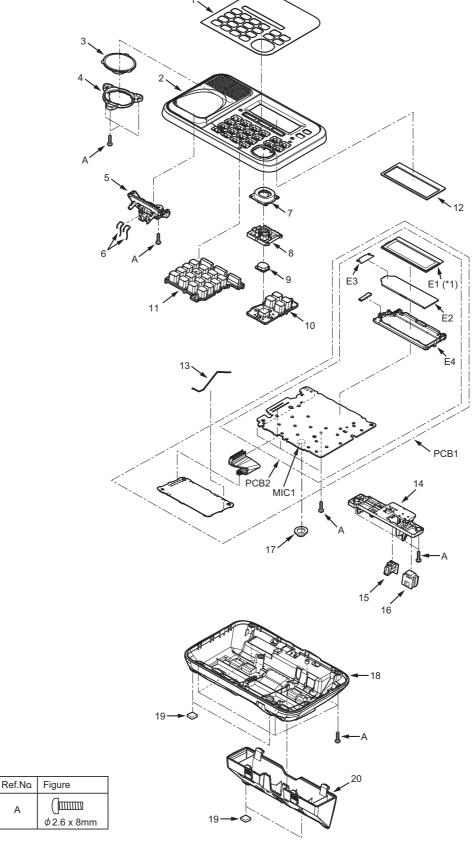
15.4.2. Bottom View

KX-TGA680 CIRCUIT BOARD (Handset_Main (Bottom View))

16 Exploded View and Replacement Parts List
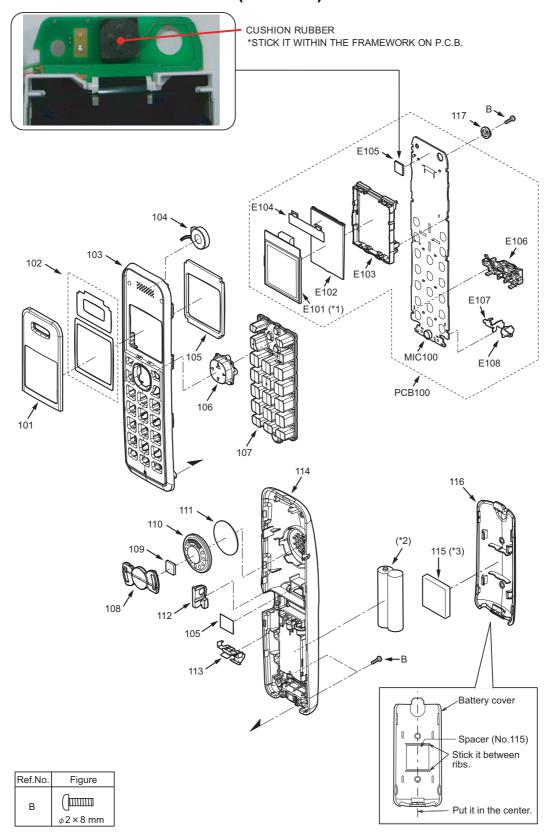
16.1. Cabinet and Electrical Parts (Base Unit)

Ref.No.	Figure
A	▢▢▢▢▢▢▢ ⌀2.6 x 8mm

Note:
   (*1) This cable is fixed by heat-sealing. Refer to **How to Replace the Base Unit LCD** (P.49).
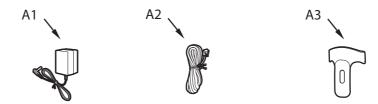
16.2. Cabinet and Electrical Parts (Handset)

CUSHION RUBBER
*STICK IT WITHIN THE FRAMEWORK ON P.C.B.

117

B

E105

E104

E106

E103

E102

E107

E101 (*1)

E108

MIC100

PCB100

104

103

102

105

106

101

107

114

116

111

110

(*2)

115 (*3)

109

108

112

105

113

B

Battery cover

Spacer (No.115)

Stick it between ribs.

Put it in the center.

Ref.No.	Figure
B	φ2 × 8 mm

Note:

(*1) This cable is fixed by heat-sealing. Refer to **How to Replace the Handset LCD** (P.51).

(*2) The rechargeable Ni-MH battery HHR-4MVT or HHR-4MRT is available through sales route of Panasonic.

(*3) Attach the SPACER (No. 115) to the exact location described above.

16.3. Accessories

A1

A2

A3

16.4. Replacement Parts List

1. RTL (Retention Time Limited)
   Note:

   The "RTL" marking indicates that its Retention Time is Limited.

   When production is discontinued, this item will continue to be available only for a specific period of time.

   This period of time depends on the type of item, and the local laws governing parts and product retention. At the end of this period, the item will no longer be available.

2. Important safety notice

   Components identified by the ⚠ mark indicates special characteristics important for safety. When replacing any of these components, only use specified manufacture's parts.

3. The S mark means the part is one of some identical parts. For that reason, it may be different from the installed part.

4. ISO code (Example: ABS-94HB) of the remarks column shows quality of the material and a flame resisting grade about plastics.

5. RESISTORS & CAPACITORS

   Unless otherwise specified;

   All resistors are in ohms (Ω) k=1000Ω, M=1000kΩ

   All capacitors are in MICRO FARADS (μF) p=μμF

   *Type & Wattage of Resistor

Type

ERC:Solid	ERX:Metal Film	PQ4R:Chip
ERDS:Carbon	ERG:Metal Oxide	ERS:Fusible Resistor
ERJ:Chip	ER0:Metal Film	ERF:Cement Resistor

Wattage

10,16:1/8W	14,25:1/4W	12:1/2W	1:1W	2:2W	3:3W

*Type & Voltage Of Capacitor

Type

ECFD:Semi-Conductor	ECCD,ECKD,ECBT,F1K,ECUV:Ceramic
ECQS:Styrol	ECQE,ECQV,ECQG:Polyester
ECUV,PQCUV, ECUE:Chip	ECEA,ECST,EEE:Electlytic
ECQMS:Mica	ECQP:Polypropylene

Voltage

ECQ Type	ECQG ECQV Type	ECSZ Type	Others		
1H:50V	05:50V	0F:3.15V	0J :6.3V	1V :35V
2A:100V	1:100V	1A:10V	1A :10V	50,1H:50V
2E:250V	2:200V	1V:35V	1C :16V	1J :16V
2H:500V		0J:6.3V	1E,25:25V	2A :100V

16.4.1. Base Unit

16.4.1.1. Cabinet and Electrical Parts

Safety	Ref. No.	Part No.	Part Name & Description	Remarks
	1	PNGP1279X1	PANEL, UPPER	PC-HB
	2	PNKM1469Z1	CABINET BODY	ABS-HB
	3	L0AA04A00028	SPEAKER	
	4	PQHR11082Z	GUIDE, SPEAKER	POM-HB
	5	PNKE1272Z1	CASE, CHARGE TERMINAL	PS-HB
	6	PNJT1144Z	CHARGE TERMINAL	
	7	PNBC1486Z1	BUTTON, NAVIGATOR KEY	ABS-HB
	8	PNHR1760Z	GUIDE, BUTTON	PS-HB
	9	PNBC1345Z1	BUTTON, MESSAGE	PMMA-HB
	10	PNJK1184Z	KEYBOARD SWITCH, TAM	
	11	PNJK1183X	KEYBOARD SWITCH, DIAL	
	12	PNYE1014Z	SPACER, CUSHION LCD	
	13	PNLA1100Z	ANTENNA	

Safety	Ref. No.	Part No.	Part Name & Description	Remarks
	14	PNHR1759Z	GUIDE, JACK	PS-HB
	15	K2ECYZ000001	JACK, DC	
	16	PQJJ1T039H	JACK, MODULAR	
	17	PQMG10025W	RUBBER PARTS, MIC	
	18	PNKF1273X1	CABINET COVER	PS-HB
	19	PNHA1013Z	RUBBER PARTS, FOOT CUSHION	
	20	PNKL1038Z1	STAND, WALL MOUNT	ABS-HB

16.4.1.2. Main P.C. Board Parts

Note:

(*1) When replacing IC611 or X501, make the adjustment using PNZZTG6841BX. Refer to **How to download the data** (P.58) of Things to Do after Replacing IC or X'tal.

(*2) When replacing the base unit LCD, See **How to Replace the Base Unit LCD** (P.49).

Safety	Ref. No.	Part No.	Part Name & Description	Remarks
	PCB1	PNWP16841BXH	MAIN P.C.BOARD ASS'Y (RTL)	
			(ICs)	
	IC302	C0DBEYY00102	IC	
	IC501	C2HBCY000126	IC	
	IC601	PNWI26841BXH	IC(FLASH)	
	IC611	PNWI16841BXH	IC(EEPROM)(*1)	
			(TRANSISTORS)	
	Q111	2SC6054JSL	TRANSISTOR(SI)	S
	Q141	B1ACGP000008	TRANSISTOR(SI)	
	Q142	B1ABDM000001	TRANSISTOR(SI)	
	Q161	DSC7003S0L	TRANSISTOR(SI)	
	Q171	2SC6054JSL	TRANSISTOR(SI)	S
	Q351	B1ADNB000003	TRANSISTOR(SI)	
	Q352	2SC6054JSL	TRANSISTOR(SI)	S
	Q353	2SC6054JSL	TRANSISTOR(SI)	S
	Q651	DRC9113Z0L	TRANSISTOR(SI)	
	Q652	DRC9113Z0L	TRANSISTOR(SI)	
	Q654	DRC9113Z0L	TRANSISTOR(SI)	
	Q661	B1ADCF000040	TRANSISTOR(SI)	
	Q662	B1GBCFGA0021	TRANSISTOR(SI)	
	Q701	2SA1576S	TRANSISTOR(SI)	S
	Q702	B1GBCFYY0020	TRANSISTOR(SI)	
			(DIODES)	
	D101	B0EDER000009	DIODE(SI)	
	D113	DA2J10100L	DIODE(SI)	
	D133	DA2J10100L	DIODE(SI)	
	D142	DY2J25000L	DIODE(SI)	
	D362	B0ECKM000008	DIODE(SI)	
	DA802	B0DDCD000001	DIODE(SI)	
			(COILS)	
	L501	G1CR10J00010	COIL	
	L803	G1C2N7Z00009	COIL	
			(RESISTOR ARRAYS)	
	RA151	EXB24V102JX	RESISTOR ARRAY	
	RA451	EXB24V222J	RESISTOR ARRAY	
	RA452	EXB24V272J	RESISTOR ARRAY	
	RA611	EXB28V332JX	RESISTOR ARRAY	
	RA651	EXB28V101JX	RESISTOR ARRAY	
	RA652	EXB28V101JX	RESISTOR ARRAY	
	RA653	EXB28V101JX	RESISTOR ARRAY	
			(VARISTOR)	
	SA101	PQVDDSS301L	VARISTOR (SURGE ABSORBER)	S
			(RESISTORS)	
	R111	PQ4R10XJ104	100k	S
	R112	PQ4R10XJ104	100k	S
	R113	D0GB103JA057	10k	
	R114	D0GA473JA021	47k	
	R121	ERJ3GEYJ394	390k	S
	R122	ERJ3GEYJ394	390k	S
	R131	PQ4R18XJ106	10M	S
	R133	ERJ3GEYJ334	330k	S

Safety	Ref. No.	Part No.	Part Name & Description	Remarks
	R141	D0GB104JA057	100k	
	R142	PQ4R18XJ272	2.7k	S
	R145	D0GA222JA021	2.2k	
	R151	D0GA104JA021	100k	
	R152	ERJ2GEJ134X	130k	S
	R160	ERJ3GEYJ821	820	S
	R161	D0GB104JA057	100k	
	R162	D0GB473JA057	47k	
	R163	D0GG390JA007	39	
	R164	D0GB272JA057	2.7k	
	R165	ERJ3GEYJ273	27k	S
	R168	D0GB472JA057	4.7k	S
	R171	D0GA221JA021	220	
	R172	ERJ2GEJ684	680k	
	R175	D0GA392JA015	3.9k	
	R176	D0GA102JA021	1k	
	R177	D0GA102JA021	1k	
	R321	ERJ2RKF1400	140	
	R322	ERJ2RKF1000	100	
	R331	ERJ2RKF6802	68k	
	R332	ERJ2RKF3302	33k	
	R351	D0GA333JA015	33k	
	R352	D0GA682JA021	6.8k	
	R354	D0GA123JA021	12k	
	R355	D0GA681JA021	680	
	R371	ERJ8GEYJ1R0	1	
	R372	ERJ8GEYJ1R0	1	
	R373	D0GA681JA021	680	
	R451	ERJ2GEYJ391	390	S
	R501	D0GB100JA057	10	
	R502	D0GA103JA021	10k	
	R503	D0GA103JA021	10k	
	R504	D0GA103JA021	10k	
	R506	D0GA103JA021	10k	
	R651	D0GA681JA021	680	
	R652	D0GA681JA021	680	
	R654	D0GA681JA021	680	
	R661	ERJ3GEYJ390	39	
	R665	D0GA821JA021	820	
	R701	D0GA332JA015	3.3k	
	R702	D0GA102JA021	1k	
	R891	ERJ2GEJ471	470	S
	R892	ERJ2GEJ471	470	S
			(CAPACITORS)	
	C101	F1K2H681A008	680p	S
	C102	F1K2H681A008	680p	S
	C111	F1J2A473A024	0.047	
	C112	F1J2A473A024	0.047	
	C113	PQCUV1A684KB	0.68	
	C120	ECUE1H102KBQ	0.001	S
	C121	F1K2H681A008	680p	S
	C122	F1K2H681A008	680p	S
	C132	ECUV1H103KBV	0.01	
	C142	ECUV1H103KBV	0.01	
	C152	ECUE1C103KBQ	0.01	
	C161	F1K1E1060001	10	
	C167	ECUV1H102KBV	0.001	
	C171	ECUV1C223KBV	0.022	
	C173	ECUE1A104KBQ	0.1	
	C175	ECUE1H561KBQ	560p	S
	C176	ECUV1C105KBV	1	
	C178	ECUV1C333KBV	0.033	
	C184	ECUV1C105KBV	1	
	C321	ECUV1C105KBV	1	
	C341	F2G0J102A148	1000	
	C342	ECUE1A104KBQ	0.1	
	C344	F2G0J102A148	1000	
	C351	ECUV1C105KBV	1	
	C451	PQCUV0J106KB	10	S
	C457	ECUE1C333KBQ	0.033	S
	C458	ECUE1C333KBQ	0.033	S
	C459	ECUE1H102KBQ	0.001	S
	C501	ECUE1A104KBQ	0.1	

Safety	Ref. No.	Part No.	Part Name & Description	Remarks
	C502	ECJ1VB0G106M	10	S
	C503	ECJ1VB0G106M	10	S
	C504	ECUE0J105KBQ	1	
	C505	ECJ1VB0G106M	10	S
	C506	ECUE0J105KBQ	1	
	C507	ECUV0J225KBV	2.2	
	C508	ECUE1H100DCQ	10p	
	C509	ECUE1H120JCQ	12p	
	C510	ECUE0J105KBQ	1	
	C511	ECJ1VB0G106M	10	S
	C513	ECUV0J225KBV	2.2	
	C515	ECUE0J105KBQ	1	
	C516	ECUE1A104KBQ	0.1	
	C517	ECUE1A104KBQ	0.1	
	C518	ECUE1A104KBQ	0.1	
	C519	ECUE1A104KBQ	0.1	
	C520	ECUE1A104KBQ	0.1	
	C521	ECUE0J105KBQ	1	
	C601	ECUE1A104KBQ	0.1	
	C611	ECUE1A104KBQ	0.1	
	C661	ECUE1A104KBQ	0.1	
	C819	ECUE1H100DCQ	10p	
	C871	F1G1H1R5A765	1.5p	
	C872	F1G1H1R3A765	1.3p	
	C873	F1G1H2R0A765	2p	
	C874	ECUE1H150JCQ	15p	S
	C891	F1G1H5R0A765	5p	
	C892	F1G1H5R0A765	5p	
	C893	ECUE1H100DCQ	10p	
	C894	ECUE1H100DCQ	10p	
	C895	F1G1H2R0A765	2p	
			(OTHERS)	
	E1	L5DYAYY00004	LIQUID CRYSTAL DISPLAY (*2)	
	E2	PNHR1762Z	TRANSPARENT PLATE, LCD	PMMA-HB
	E3	PNHX1617Z	COVER, REFLECTOR SHEET	
	E4	PNHR1761Z	GUIDE, LCD	ABS-HB
	P101	D4DAY220A022	THERMISTOR (POSISTOR)	
⚠	F301	K5H302Y00003	FUSE	
	X501	H0J138500011	CRYSTAL OSCILLATOR (*1)	

16.4.1.3. Operational P.C. Board Parts

Safety	Ref. No.	Part No.	Part Name & Description	Remarks
	PCB2	PNWP2TG6841H	OPERATIONAL P.C.BOARD ASS'Y (RTL)	
			(LEDS)	
	LED901	B3AAB0000347	LED	
	LED902	B3AAB0000347	LED	
	LED904	B3AAB0000347	LED	
			(RESISTOR)	
	R906	ERJ3GSYJ330	33	S
			(CAPACITORS)	
	C901	ECUE0J105KBQ	1	
	C902	ECUV1C105KBV	1	
	C912	ECUE1H100DCQ	10p	
			(OTHER)	
	MIC1	L0CBAY000123	MICROPHONE	

16.4.1.4. LED Board Parts

Safety	Ref. No.	Part No.	Part Name & Description	Remarks
			(LED)	
	WLED	B3AFB0000370	LED	

16.4.2. Handset

16.4.2.1. Cabinet and Electrical Parts

Safety	Ref. No.	Part No.	Part Name & Description	Remarks
	101	PNGP1272Z1	PANEL, LCD	PMMA-HB
	102	PNYE1106Z	TAPE, DOUBLE SIDED	
	103	PNKM1467Z1	CABINET BODY	ABS-HB
	104	L0AD01A00026	RECEIVER	
	105	PNYE1107Z	SPACER, CUSHION LCD	
	106	PNBC1483Z1	BUTTON, NAVIGATOR KEY	ABS-HB
	107	PNJK1181X	KEYBOARD SWITCH	
	108	PNHR1757Z	GUIDE, SPEAKER	ABS-HB
	109	PQHG10729Z	RUBBER PARTS, RECEIVER	
	110	L0AA02A00120	SPEAKER	
	111	PNHS1502Z	SPACER, SPEAKER NET	
	112	PNKE1269Z1	COVER, EP CAP	
	113	PNJC1018Z	BATTERY TERMINAL	
	114	PNKF1271Z1	CABINET COVER	ABS-HB
	115	PNHS1466Z	SPACER, BATTERY	
	116	PNKK1076Z1	LID, BATTERY	ABS-HB
	117	PNHR1644Z	SPACER	PS-HB

16.4.2.2. Main P.C. Board Parts

Note:

(*1) Reconfirm the model No. written on the handset's name plate when replacing PCB100. Because the model No. of the optional handset may differ from the included handset.

(*2) When replacing IC3 or X1, make the adjustment using PNZZTG6841BX. Refer to **Handset** (P.59) of Things to Do after Replacing IC or X'tal.

(*3) When replacing the handset LCD, See **How to Replace the Handset LCD** (P.51).

Safety	Ref. No.	Part No.	Part Name & Description	Remarks
	PCB100	PNWPGA680BXR	MAIN P.C.BOARD ASS'Y (RTL) (*1)	
			(ICs)	
	IC1	C2HBCY000124	IC	
	IC3	PNWIGA680BXR	IC (EEPROM) (*2)	
	IC4	C0DBZYY00357	IC	
			(TRANSISTORS)	
	Q2	B1ADCF000040	TRANSISTOR(SI)	
	Q3	B1ABGE000011	TRANSISTOR(SI)	
	Q4	B1ADCF000040	TRANSISTOR(SI)	
	Q6	DRC9113Z0L	TRANSISTOR(SI)	
	Q9	2SC6054JSL	TRANSISTOR(SI)	S
	Q10	B1ADNB000003	TRANSISTOR(SI)	
	Q11	2SC6054JSL	TRANSISTOR(SI)	S
	Q12	B1ADCF000040	TRANSISTOR(SI)	
			(DIODES)	
	D13	B0BC4R3A0006	DIODE(SI)	
	D14	B0BC4R3A0006	DIODE(SI)	
			(LEDS)	
	LED1	B3ACB0000190	LED	
	LED2	B3ACB0000190	LED	
	LED3	B3ACB0000190	LED	
	LED4	B3ACB0000190	LED	
	LED5	B3ACB0000190	LED	
	LED6	B3ACB0000190	LED	
	LED20	B3AFB0000561	LED	
			(COIL)	
	L801	G1C2N7Z00009	COIL	
			(RESISTOR ARRAYS)	
	RA2	D1H83314A013	RESISTOR ARRAY	S
	RA3	EXB24V331J	RESISTOR ARRAY	
	RA4	EXB24V332JX	RESISTOR ARRAY	
	RA5	EXB28V332JX	RESISTOR ARRAY	
			(IC FILTER)	

Safety	Ref. No.	Part No.	Part Name & Description	Remarks
	L3	J0JDC0000045	IC FILTER	
			(RESISTORS)	
	R2	D0GA303JA021	30k	
	R3	D0GA152JA021	1.5k	
	R4	D0GA473JA021	47k	
	R6	D0GA103JA021	10k	
	R7	D0GA104JA021	100k	
	R8	ERJ8GEYJ4R3V	4.3	S
	R9	D0GA303JA021	30k	
	R10	ERJ3GEYJ1R0	1	S
	R11	D0GA681JA021	680	
	R12	D0GA183JA015	18k	
	R13	D0GA103JA021	10k	
	R19	ERJ2RKF2003X	200k	S
	R20	ERJ2RKF1003X	100k	S
	R21	D0GA104JA021	100k	
	R22	D0GA332JA015	3.3k	
	R23	ERJ2GEYJ391	390	S
	R24	ERJ2GEJ100	10	S
	R25	D0GA222JA021	2.2k	
	R26	D0GA332JA015	3.3k	
	R27	D0GA222JA021	2.2k	
	R28	D0GA222JA021	2.2k	
	R31	ERJ2RKF1003X	100k	S
	R32	D0GA104JA021	100k	
	R33	ERJ2RKF1003X	100k	S
	R34	ERJ2GEYJ391	390	S
	R45	D0GBR10JA113	0.1	
	R66	D0GA103JA021	10k	
	R67	D0GA103JA021	10k	
	R68	D0GA103JA021	10k	
	R69	D0GA103JA021	10k	
	R70	D0GA101JA021	100	
	R72	ERJ2GE0R00	0	S
	L8	ERJ2GEJ100	10	S
			(CAPACITORS)	
	C2	F1J0J2260002	22	
	C3	F1J0J2260002	22	
	C5	ECUE1A104KBQ	0.1	
	C6	ECUE1A104KBQ	0.1	
	C11	ECUE1A104KBQ	0.1	
	C12	ECJ1VB0G106M	10	S
	C13	ECUE1A104KBQ	0.1	
	C14	ECUV1C393KBV	0.039	
	C15	ECUE1H390JCQ	39p	
	C16	F1J0J2260002	22	
	C17	ECUE1H100DCQ	10p	
	C18	ECUE1H100DCQ	10p	
	C20	ECJ1VB0G106M	10	S
	C21	ECUE0J105KBQ	1	
	C22	ECUE1A104KBQ	0.1	
	C23	ECUE1A104KBQ	0.1	
	C24	ECUE0J105KBQ	1	
	C25	ECUV1A225KBV	2.2	S
	C26	ECJ1VB0G106M	10	S
	C27	ECUE1H102KBQ	0.001	S
	C29	ECUE0J105KBQ	1	
	C30	ECUE0J105KBQ	1	
	C31	ECJ1VB0G106M	10	S
	C32	ECUE0J105KBQ	1	
	C33	ECUE1A104KBQ	0.1	
	C34	ECUE1H390JCQ	39p	
	C36	ECUE1A104KBQ	0.1	
	C37	ECJ1VB0G106M	10	S
	C40	ECUE1A104KBQ	0.1	
	C41	ECUE1A104KBQ	0.1	
	C43	ECUE1A104KBQ	0.1	
	C44	ECUE0J105KBQ	1	
	C45	ECUE1A104KBQ	0.1	
	C46	ECUE1H100DCQ	10p	S
	C51	ECJ1VB0G106M	10	S
	C52	ECUE1H100DCQ	10p	
	C53	ECUE1H120JCQ	12p	

Safety	Ref. No.	Part No.	Part Name & Description	Remarks
	C56	ECUE0J105KBQ	1	
	C57	ECUE0J105KBQ	1	
	C58	ECUE0J105KBQ	1	
	C68	ECUE0J105KBQ	1	
	C69	ECUE1A104KBQ	0.1	
	C70	ECUE1H680JCQ	68p	
	C71	ECUE1H680JCQ	68p	
	C79	ECUE1H101JCQ	100p	
	C80	ECUV1C393KBV	0.039	
	C90	ECUE1A104KBQ	0.1	
	C91	ECUV1C105KBV	1	
	C92	ECUE0J105KBQ	1	
	C96	ECUE1H100DCQ	10p	
	C97	ECUE1H100DCQ	10p	
	C801	F1G1H2R0A765	2p	
	C802	ECUE1H100DCQ	10p	
	C807	F1G1H2R0A765	2p	
	C808	F1G1H1R3A765	1.3p	
	C809	F1G1H1R5A765	1.5p	
	C810	ECUE1H150JCQ	15p	S
			(OTHERS)	
	MIC100	L0CBAY000053	MICROPHONE	
	E101	L5DYBYY00001	LIQUID CRYSTAL DISPLAY (*3)	S
	E102	PNHR1756Z	TRANSPARENT PLATE, LCD	PMMA-HB
	E103	PNHR1755Z	GUIDE, LCD	ABS-HB
	E104	PNHX1618Z	COVER, LCD SHEET	
	E105	PQHG10729Z	RUBBER PARTS, RECEIVER	
	E106	PNVE1011Z	BATTERY TERMINAL	ABS-HB
	E107	PNJT1141Z	CHARGE TERMINAL (L)	
	E108	PNJT1140Z	CHARGE TERMINAL (R)	
	CN4	K2HD103D0001	JACK	
⚠	F1	K5H252Y00002	FUSE	
	X1	H0J138500003	CRYSTAL OSCILLATOR (*2)	S

16.4.3. Accessories

Note:
You can download and refer to the Operating Instructions (Instruction book) on TSN Server.

Safety	Ref. No.	Part No.	Part Name & Description	Remarks
⚠	A1	PNLV226BX0Z	AC ADAPTOR (for Base Unit)	
	A2	PQJA10075Z	CORD, TELEPHONE	
	A3	PNKE1268Z1	HANGER, BELT CLIP	ABS-HB

16.4.4. Screws

Safety	Ref. No.	Part No.	Part Name & Description	Remarks
	A	XTB26+8GFJ	TAPPING SCREW	
	B	XTB2+8GFJ	TAPPING SCREW	

16.4.5. Fixtures and Tools

Note:
(*1) See **Equipment Required** (P.52), and **The Setting Method of JIG** (P.52)

(*2) When replacing the Handset LCD, See **How to Replace the Handset LCD** (P.51)

Safety	Ref. No.	Part No.	Part Name & Description	Remarks
		PQZZ1CD300E	JIG CABLE (*1)	
		PNZZTG6841BX	BATCH FILE CD-ROM (*1)	
		PQZZ430PIR	TIP OF SOLDERING IRON (*2)	
		PQZZ430PRB	RUBBER OF SOLDERING IRON (*2)	

SH
KXTG6841BXB
KXTGA680BXB